

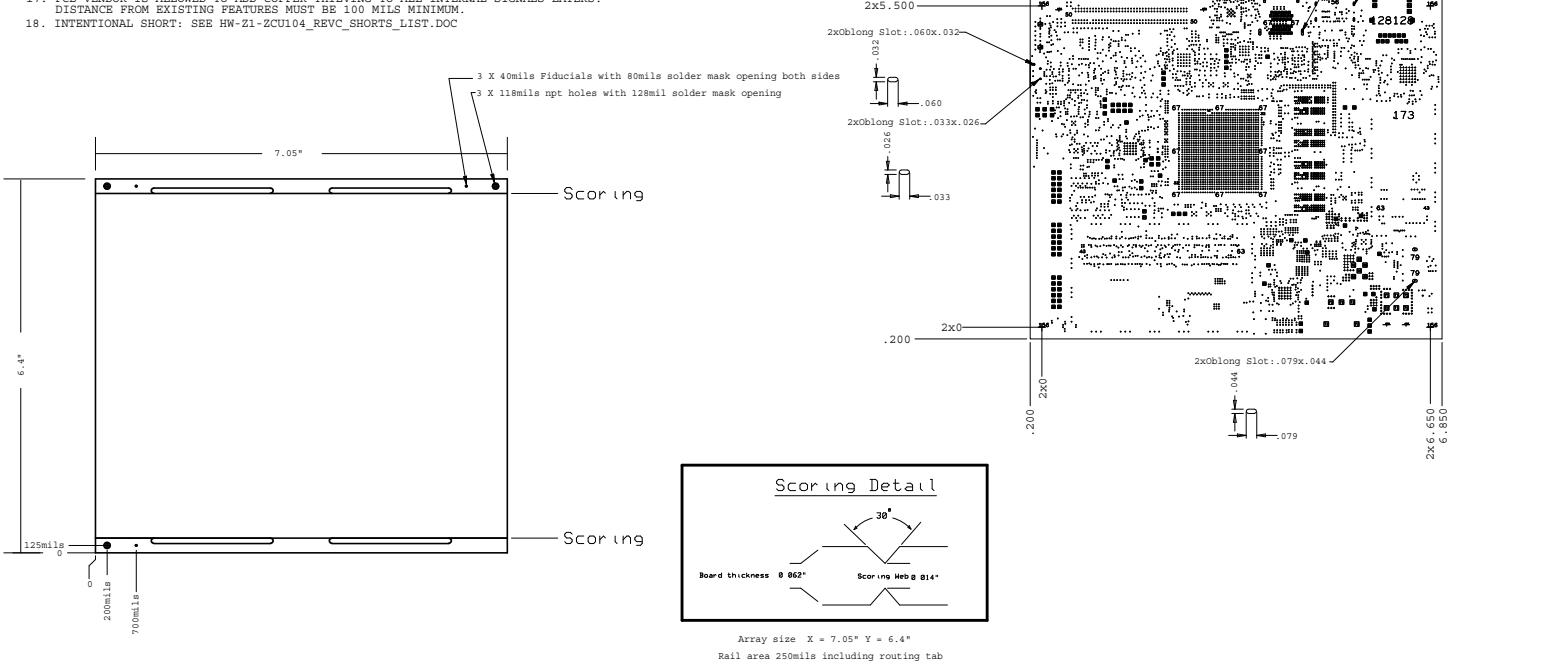
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
B	PROTOTYPE	08/30/17	
B	PROTOTYPE	08/30/17	
C	PROTOTYPE	11/27/17	
1.0	PROTOTYPE	02/10/18	
01	PROTOTYPE	02/08/18	

NOTES: (UNLESS OTHERWISE SPECIFIED)  
THIS FAB SHOULD BE "ROHS COMPLIANT".

1. FABRICATE TO IPC-A-600, CURRENT REVISION
  2. BOARD SHALL MEET THE INSPECTION CRITERIA OF
    - a- ACCEPTABILITY AS PER IPC-A-600 (LATEST REVISION) CLASS II
    - b- QUALIFICATION AND PERFORMANCE AS PER IPC-6012 (LATEST REVISION) CLASS II.
  3. MATERIAL: ISOLA FR408H (ROHS COMPLIANT MATERIAL) OR EQUIVALENT. GLASS TRANSITION TEMPERATURE MUST MEET OR EXCEED THE TEMPERATURE EXHIBITED WITH HIGH TEMPERATURE PROCESSES ASSOCIATED WITH LEAD FREE ASSEMBLY.
  4. APPLY SOLDER MASK OVER BARE COPPER (SMOBC) IAW IPC-SM-840, BOTH SIDES, USING LPI, COLOR GREEN.
  5. LPI SOLDER MASK TAIYO PSR4000 (ROHS COMPLIANT MATERIAL) OR EQUIVALENT WILL BE USED ON BOTH SIDES.
  6. SOLDER MASK REGISTRATION TO BE WITHIN DIAMETRICAL TRUE POSITION OF + / - 0.002"WITH APPLICABLE HOLE / PAD.
  7. FINISH: GOLD IMMERSION.
  8. SILKSCREEN USING WHITE - HAVEN PC421 ( NON-CONDUCTIVE OR EQUIVALENT ROHS COMPLIANT MATERIAL) BOTH SIDES DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON SOLDER LANDS IS NOT ACCEPTABLE.
  9. VENDOR LOGO AND DATE CODE TO BE MARKED SOLDER SIDE IN SILKSCREEN. MAXIMUM HEIGHT 0.12 INCHES.
  10. 100% ELECTRICAL TEST REQUIRED FOR CONTINUITY. BOARD SHALL HAVE A UL-RATING OF 94V-0. UL SYMBOL AND RATING SHALL BE MARKED SOLDER SIDE IN SILKSCREEN.

11. REMOVE ALL UNUSED PADS FROM INTERNAL LAYERS.

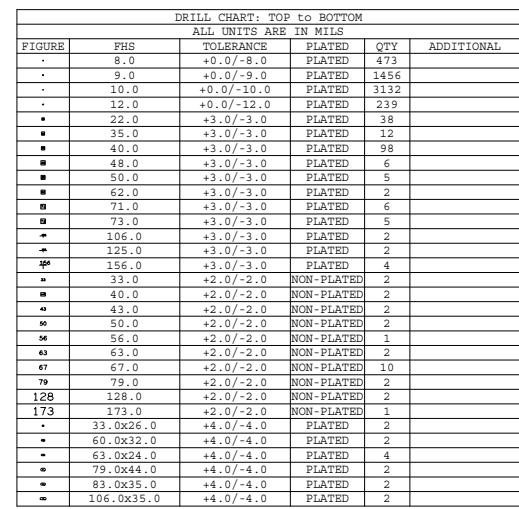
12. 274X GERBER/ODB++ USED FOR FAB MUST BE VERIFIED AGAINST THE PROVIDED IPC356 NETLIST. COPPER SLIVERS THAT ARE LESS THAN 0.003" IN WIDTH BETWEEN ANTI-PAD TO PLANE EDGE, ANTI-PAD TO SPLIT PLANE AND ANTI-PAD TO ANTI-PAD MUST BE REMOVED FROM THE MANUFACTURING ARTWORK. A NETLIST COMPARISON MUST BE PASSED WITH NO VIOLATION AFTER THE REMOVAL OF SLIVERS. ANY REQUIREMENT FOR SLIVER REMOVAL ABOVE OR EQUAL TO THE 0.003" COPPER WIDTH MUST BE ADDRESSED AND APPROVED IN WRITING BY SUPPLIER.
  13. VIAS ARE SUPPOSED TO BE DIRECTLY CONNECTED TO RESPECTIVE PLANE.
  14. FOR IMPEDANCE CONTROL DETAILS REFER TO STACK-UP DOCUMENT INCLUDED ZCU106\_HR408BUILDF.pdf DATA.
  15. VIA IN PAD TECHNOLOGY USED:  
VIA FILL IS REQUIRED: THIS IS A VIA IN PAD JOB, ALL VIA IN PAD LOCATIONS, LISTED IN "VIA\_EPOXY\_T" AND "VIA\_EPOXY\_BOT" MUST BE COMPLETELY FILLED" WITH PETERS PP-2795 OR EQUIVALENT 100% SOLIDS FILM PLANARIZED, AND PLATED OVER WITH" COPPER AND SURFACE FINISH.
  16. ALL VIA DRILLS LISTED IN "VIA\_PLUG\_TOP AND VIA\_PLUG\_BOT" MUST BE PLUGGED AND COVERED WITH SOLDER
  17. PCB VENDOR IS ALLOWED TO ADD COPPER THICKENING TO ALL INTERNAL SIGNALS LAYERS



IMPEDANCE CHAR

LAYER	TOP SIDE	EDGE-COUPLED DIFFERENTIAL	NECK VALUES		TOP SIDE
			TRACE WIDTH/Z CMHS	TRACE LENGTH/Z CMHS	
LAYER 1	TOP SIDE	6.2 MIL	36	0.2 MIL/0.2 MIL	56
		6.5 MIL	39	0.2 MIL/0.2 MIL	56
		7.5 MIL	50	0.2 MIL/0.2 MIL	56
LAYER 3	TOP SIDE	6.2 MIL	36	1.5 MIL/1.5 MIL	66
		6.5 MIL	39	1.5 MIL/1.5 MIL	76
		7.5 MIL	50	2.5 MIL/2.5 MIL	86
LAYER 5	TOP SIDE	6.2 MIL	36	1.5 MIL/1.5 MIL	66
		6.5 MIL	39	1.5 MIL/1.5 MIL	76
		7.5 MIL	50	2.4 MIL/2.4 MIL	100
LAYER 7	TOP SIDE	6.2 MIL	36	1.5 MIL/1.5 MIL	66
		6.5 MIL	39	1.5 MIL/1.5 MIL	76
		7.5 MIL	50	2.4 MIL/2.4 MIL	100
LAYER 12	TOP SIDE	6.2 MIL	36	0.5 MIL/0.5 MIL	56
		6.5 MIL	39	0.5 MIL/0.5 MIL	56
		7.5 MIL	50	1.5 MIL/1.5 MIL	86
LAYER 14	TOP SIDE	6.2 MIL	36	0.5 MIL/0.5 MIL	56
		6.5 MIL	39	0.5 MIL/0.5 MIL	76
		7.5 MIL	50	1.5 MIL/1.5 MIL	86
BOTTOM	TOP SIDE	6.2 MIL	36	0.5 MIL/0.5 MIL	56
		6.5 MIL	39	0.5 MIL/0.5 MIL	56
		7.5 MIL	50	0.5 MIL/0.5 MIL	100

CROSSED IMPEDANCE CALL OUTS DO NOT EXIST IN PROVIDED DATA. IGNORE THEM



TOTAL HOLES: 55

SURFACE - AIR 0 MIL  
DIELECTRIC - CONFORMAL COAT 0.8 MIL  
TOP CONDUCTOR - PLATED\_COPPER\_FOIL 2 MIL  
DIELECTRIC - FR408HR\_1X1080PP 3.5 MIL

02 GND1 PLANE - PLATED COPPER FOIL 0.6 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

03 SIG1 CONDUCTOR - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_1XZ113PP 2.89 MIL

04 GND2 PLANE - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

05 SIG2 CONDUCTOR - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_1XZ113PP 2.89 MIL

06 GND3 PLANE - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

07 SIG3 CONDUCTOR - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_1XZ113PP 2.89 MIL

08 GND4 PLANE - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

09\_PWR1 PLANE - 1OZ\_COPPER 1.2 MIL  
DIELECTRIC - FR408HR\_2X106PP 3.54 MIL

10\_PWR2 PLANE - 1OZ\_COPPER 1.2 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

11\_GND5 PLANE - 1OZ\_COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_1X2113PP 2.89 MIL

12\_SIG4 CONDUCTOR - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

13\_GND6 PLANE - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_1X2113PP 2.89 MIL

14\_SIG5 CONDUCTOR - 05OZ COPPER 0.6 MIL  
DIELECTRIC - FR408HR\_CORE 3 MIL

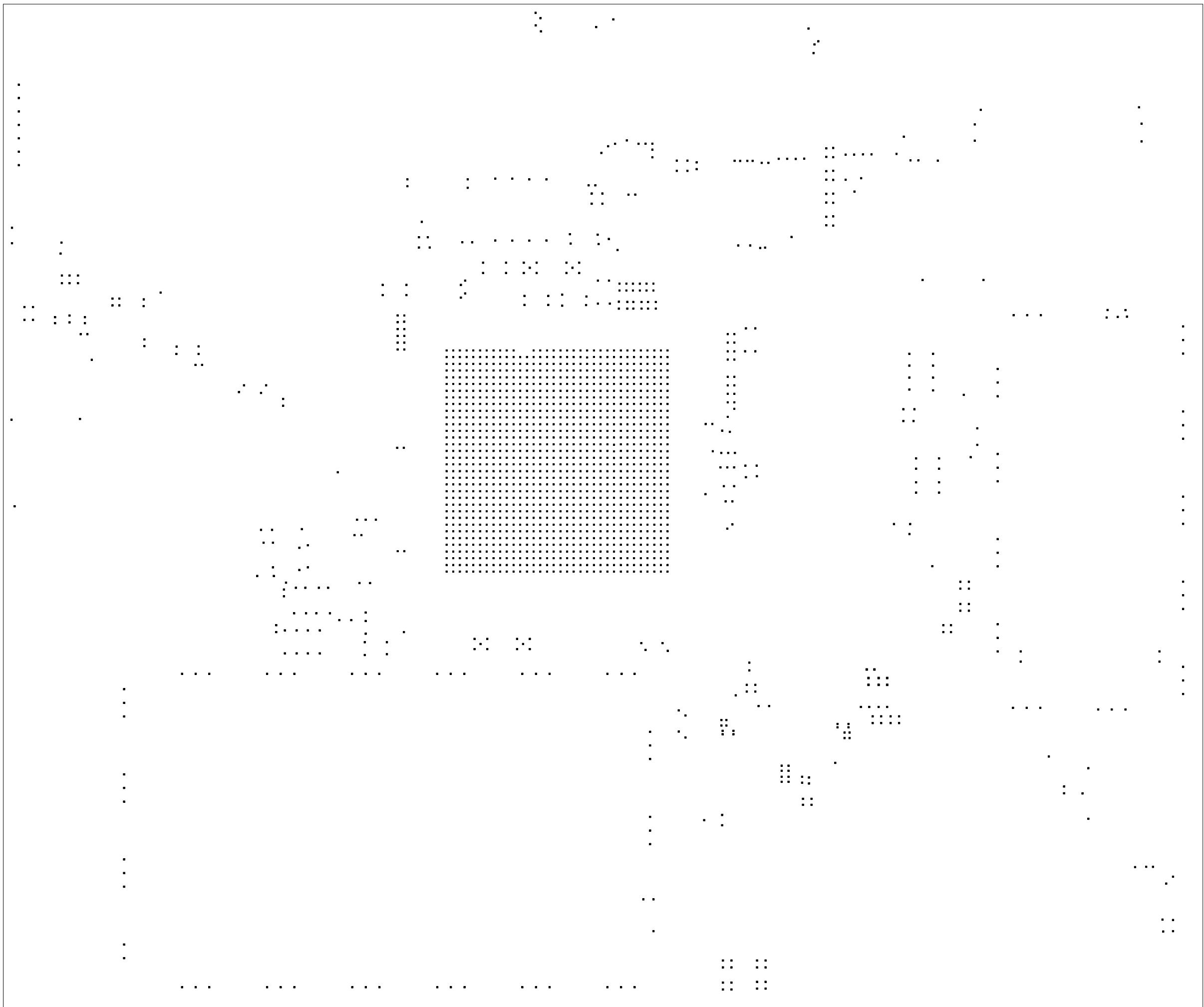
15\_GND7 PLANE - PLATED COPPER\_FOIL 0.6 MIL  
DIELECTRIC - FR408HR\_1X1080PP 3.5 MIL

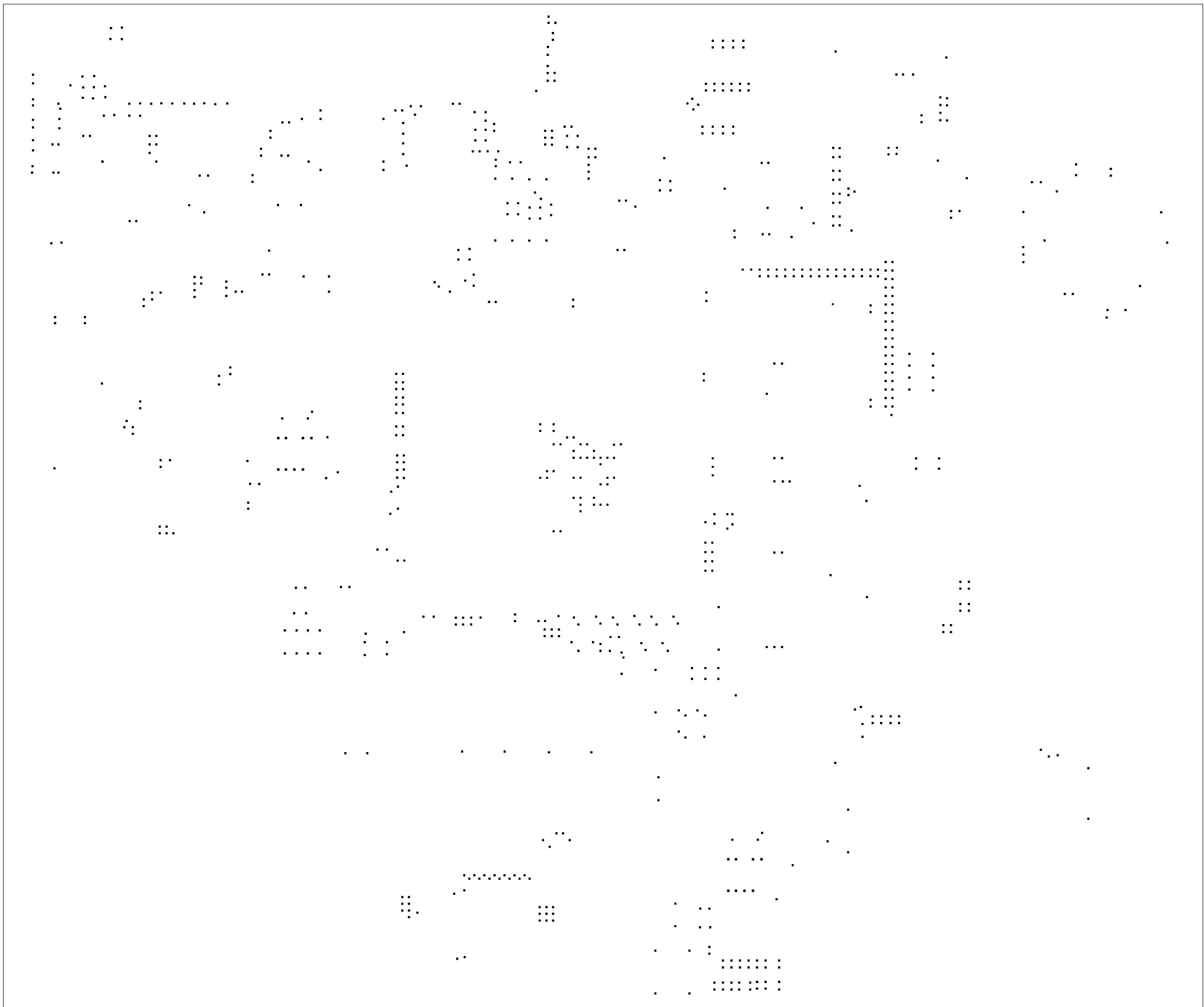
BOTTOM CONDUCTOR - PLATED COPPER FOIL 2 MIL  
DIELECTRIC - CONFORMAL\_COAT 0.8 MIL  
SURFACE - AIR 0 MIL

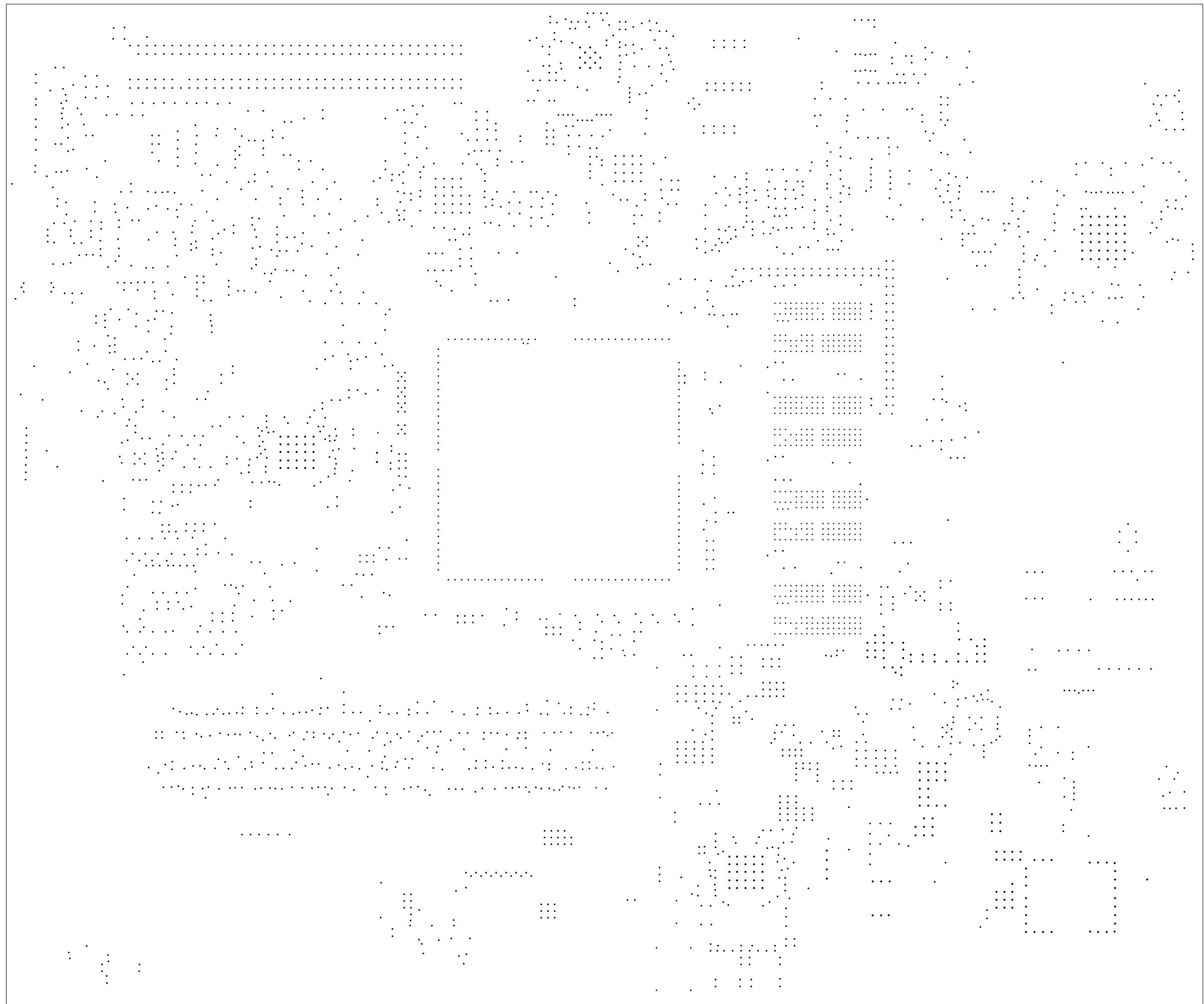
DESIGN CROSS SECTION CHART  
TOTAL THICKNESS 61.19 MIL

TOTAL THICKNESS 61.19 MIL +/- 5 MIL (8%)

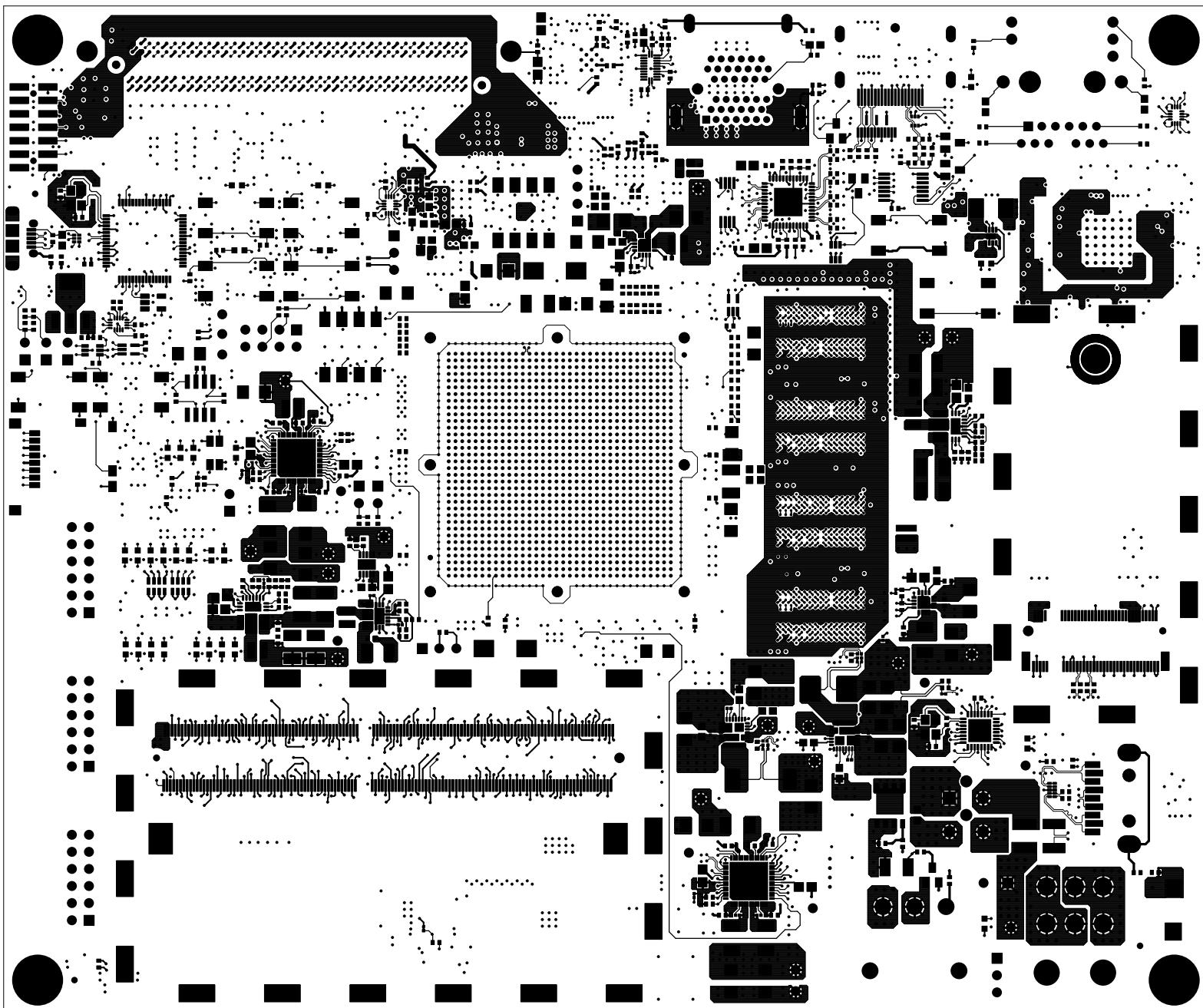
UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	 <b>XILINX®</b> 2100 LOGIC DR. SAN JOSE, CA 95124 HWCP - HARDWARE & CONFIGURATION PLATFORMS <b>FABRICATION DRAWING</b> <b>HW-Z1-ZCU104</b> PCB, ROHS COMPLIANT				
DIMENSIONS ARE IN INCHES	DRAWN	Rocket EMS	02-10-18				
TOLERANCES ON:	CHECKED	Brian Forsse					
2 PL DECIMALS +/- .010	ENGRG	Brian Forsse	02-10-18				
3 PL DECIMALS +/- .005	ISSUED						
ANGLES +							
FRACTIONS +							
				SIZE	FSCM NO	DWG NO	REV: 01
				D		1280961	VER: 1.0
				SCALE	NONE		SHEET 1 OF 1



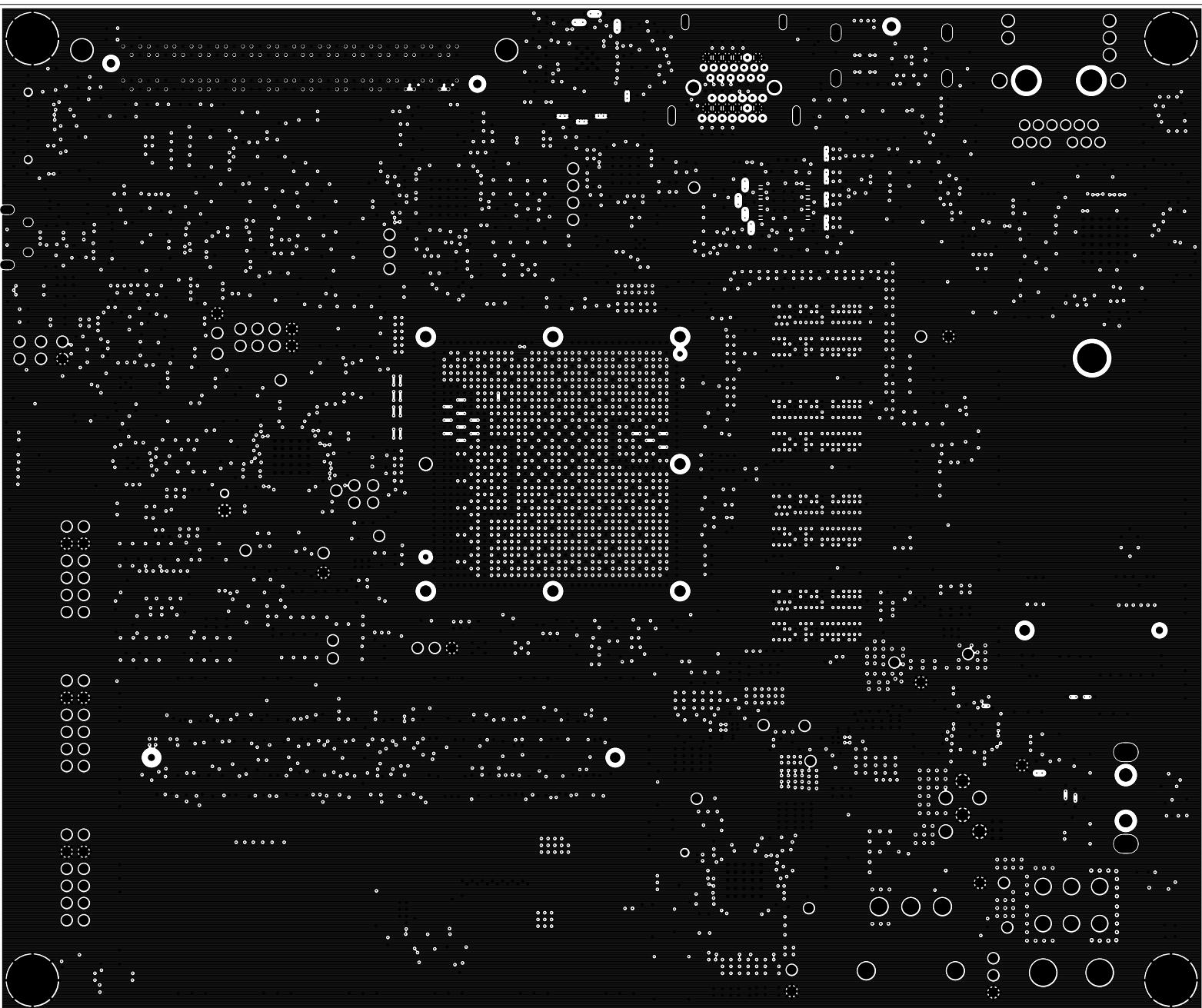




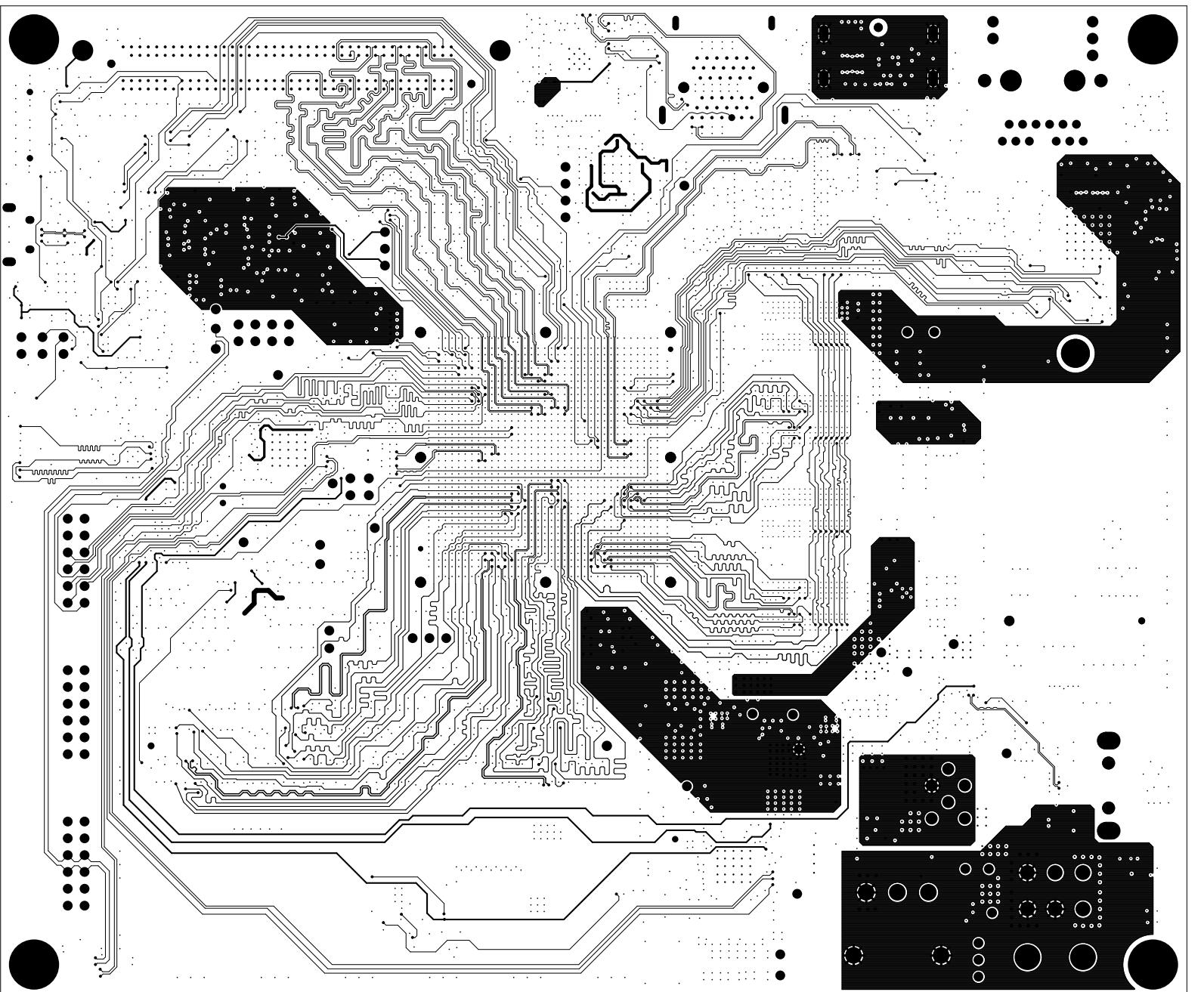




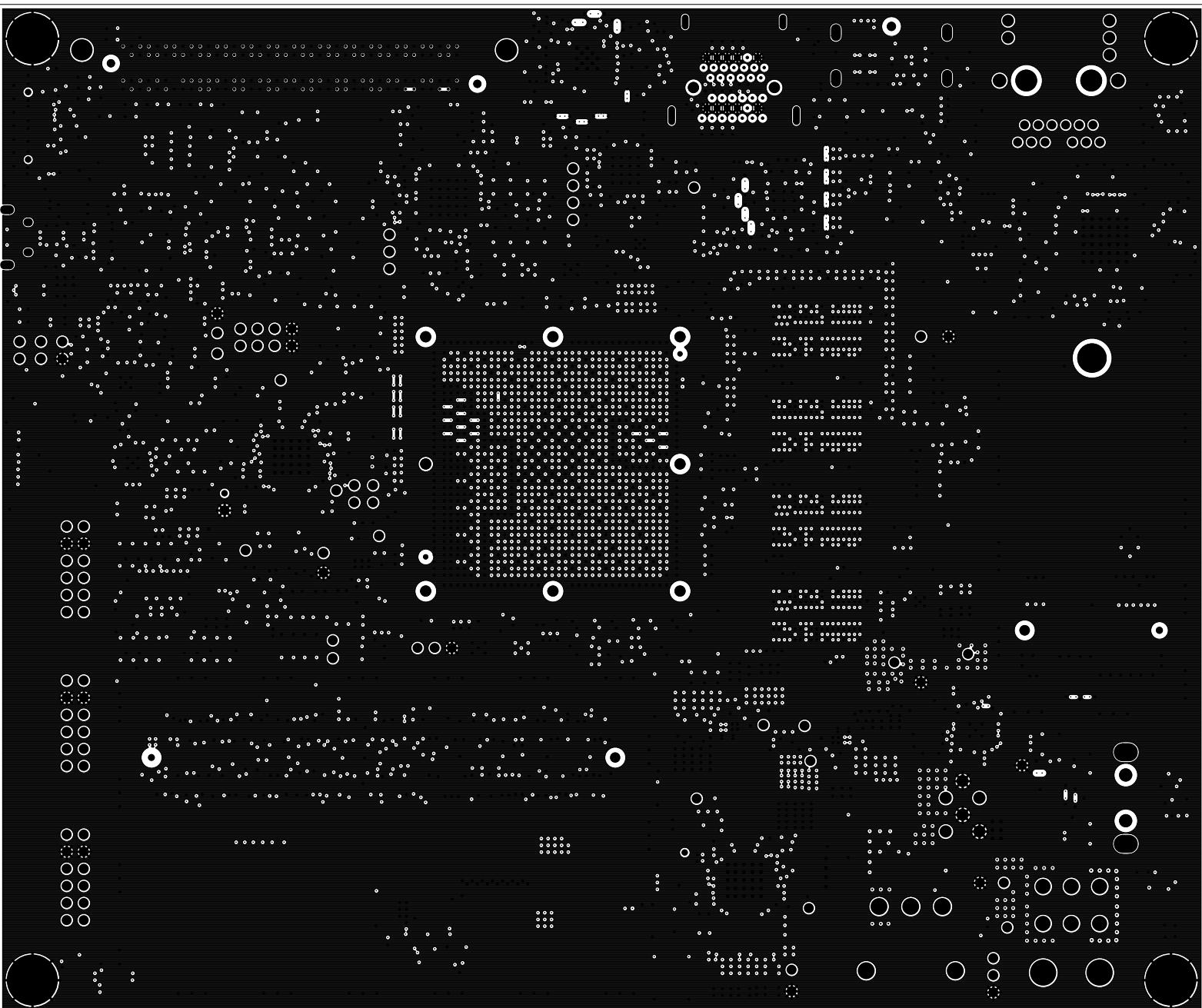
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 01 OF 22 LAYER: TOP	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



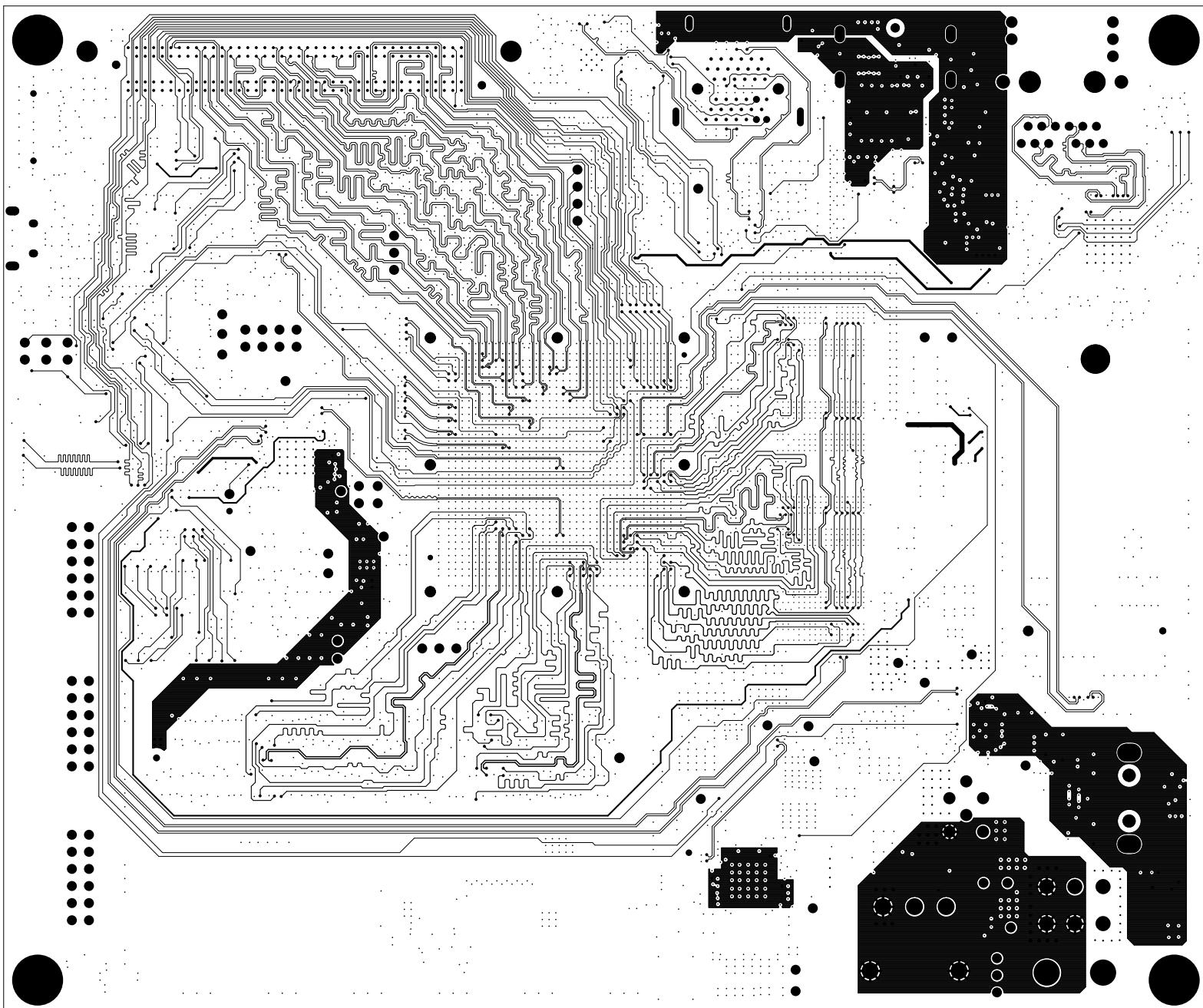
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 02 OF 22 LAYER: GND1	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



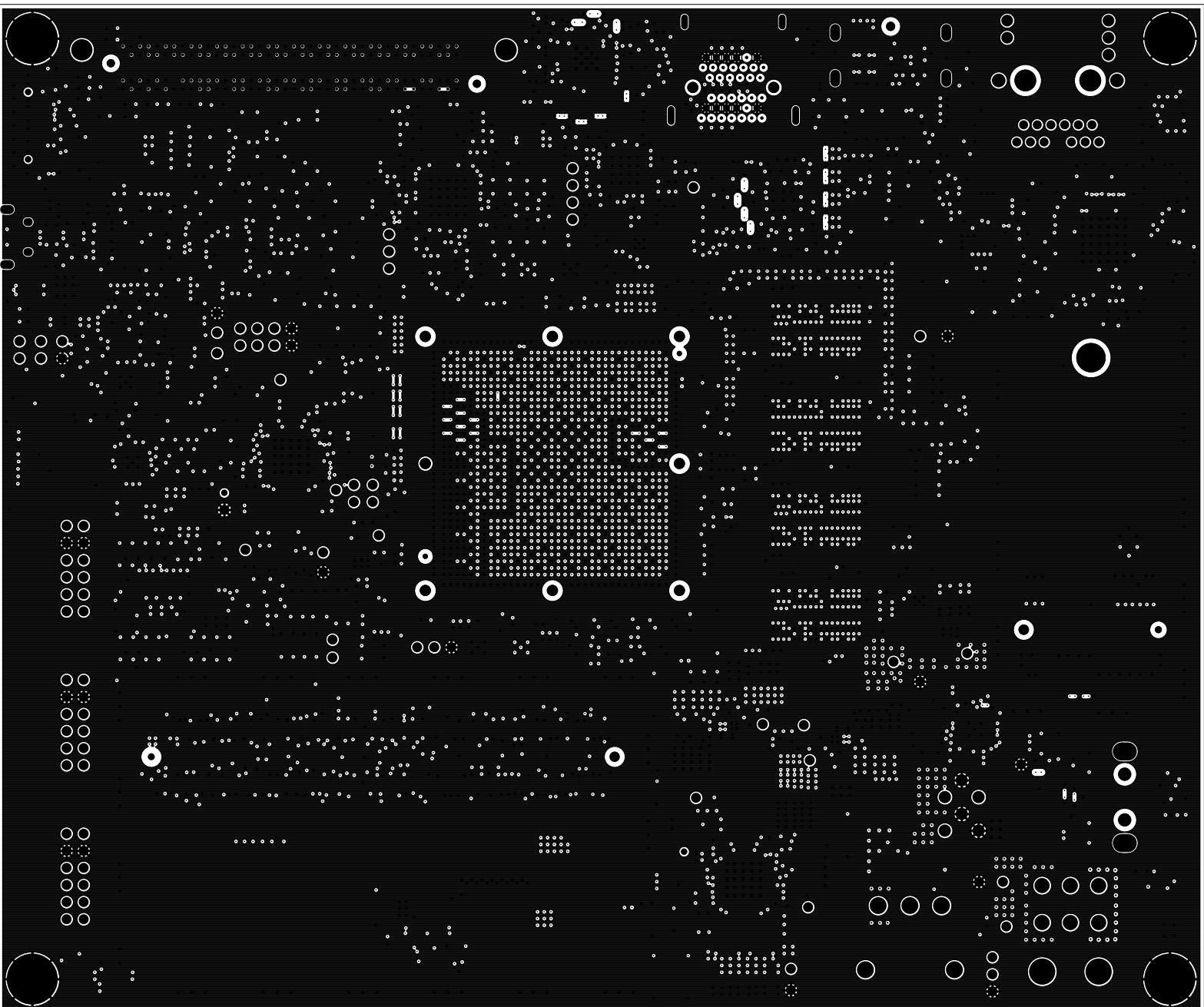
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PCB #	1280961
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SCAREY	PHONE: 4088794451
SHEET 03 OF 22 LAYER: SIG1	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



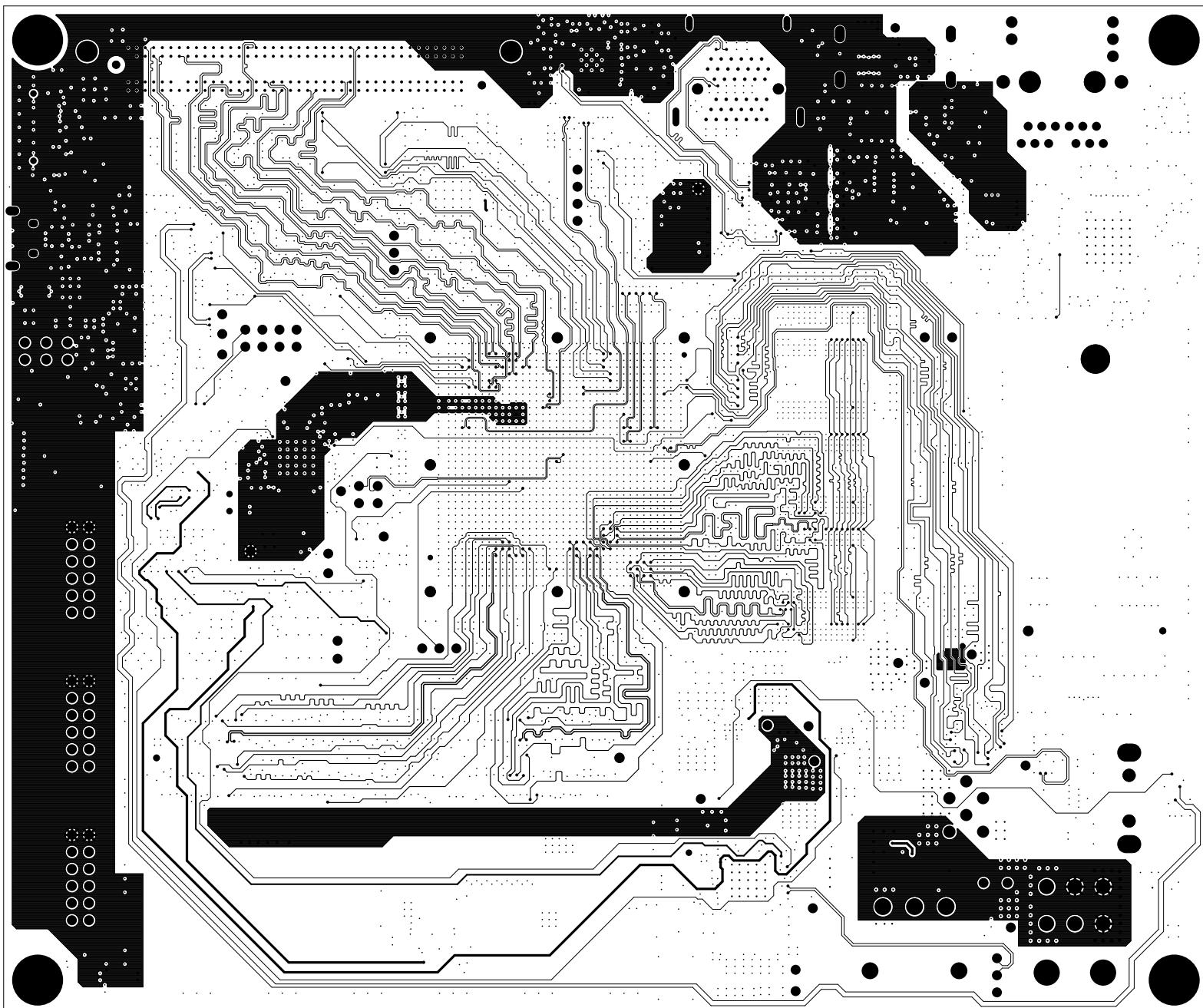
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 04 OF 22 LAYER: GND2	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



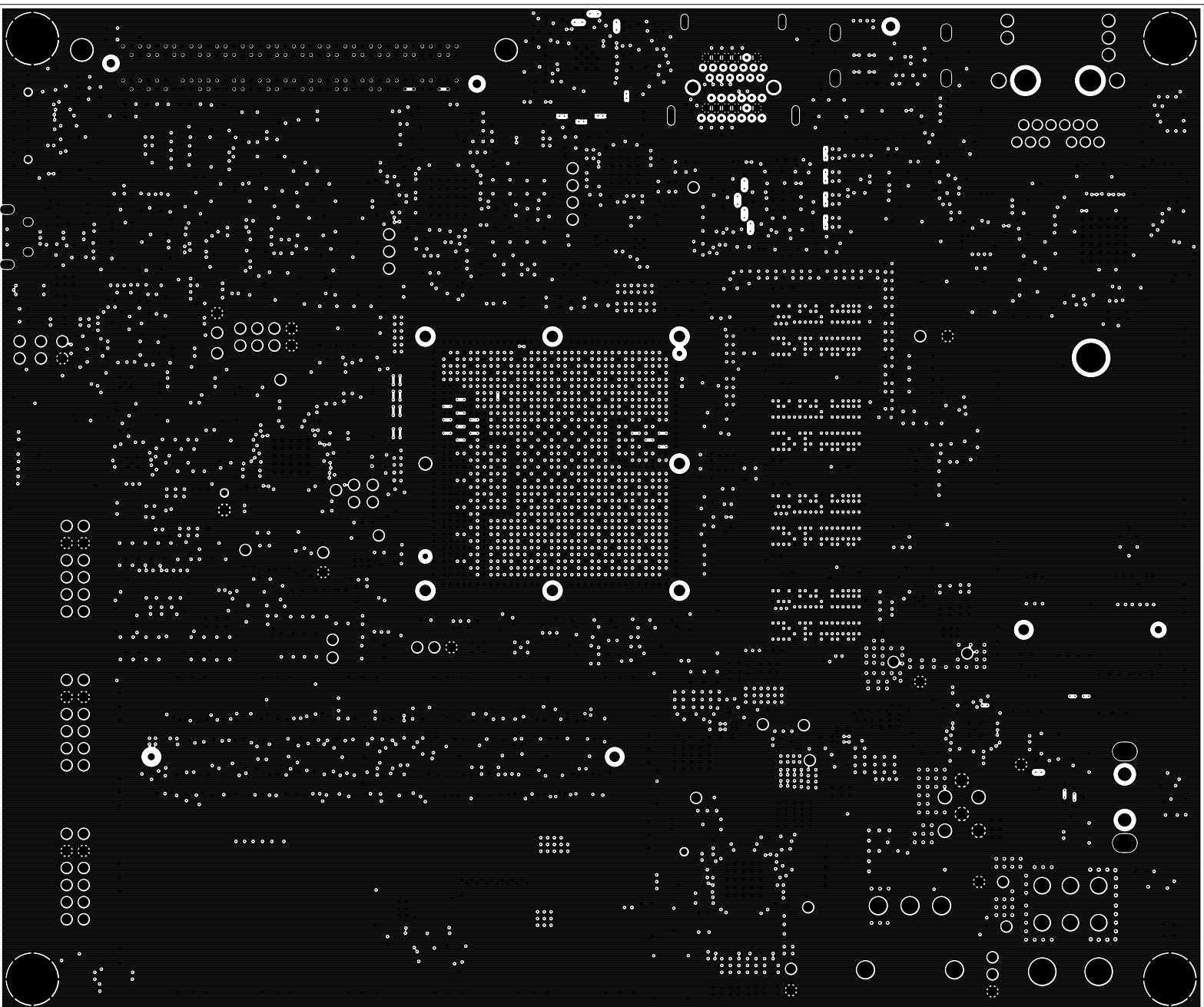
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Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 05 OF 22 LAYER: SIG2	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



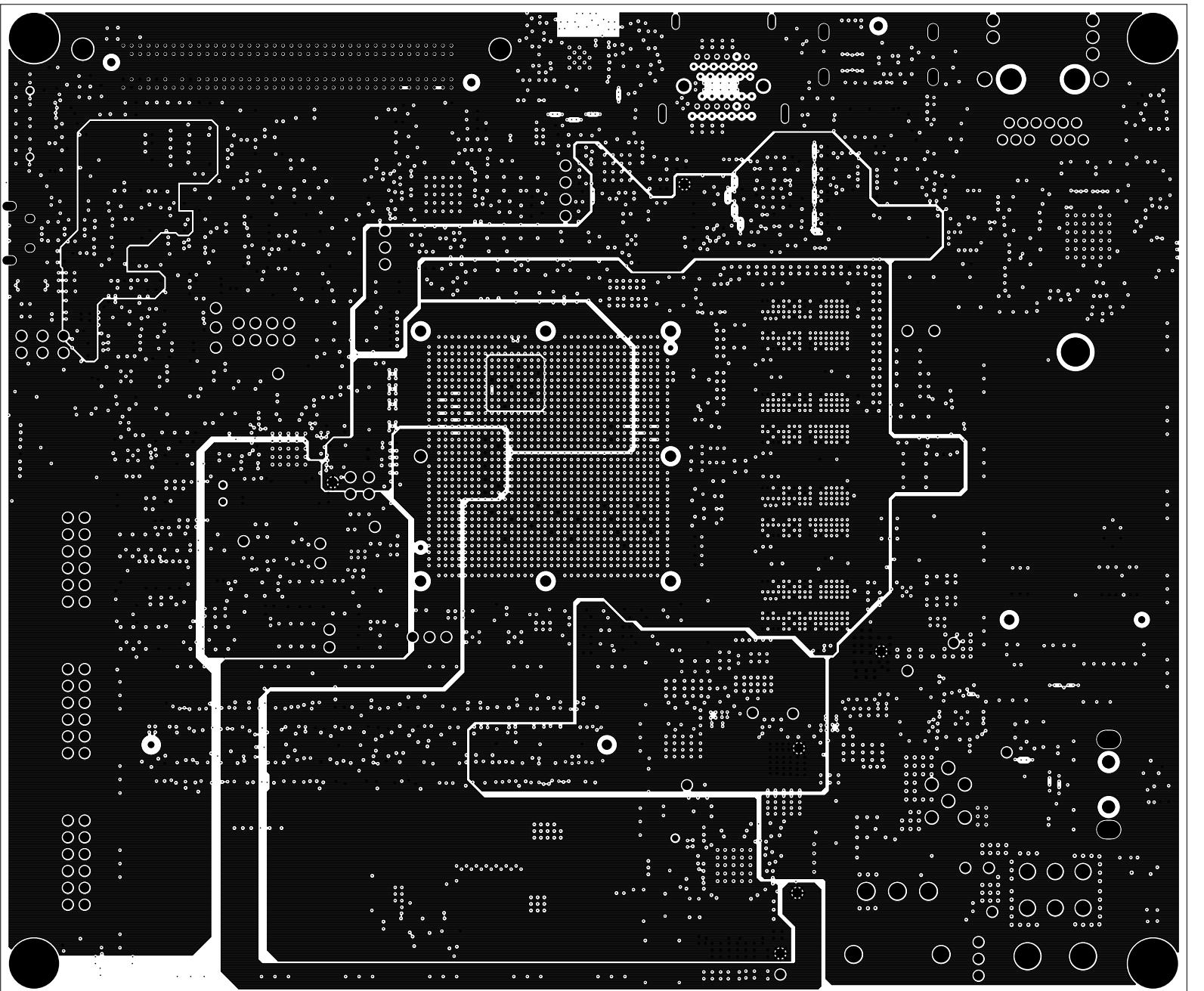
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
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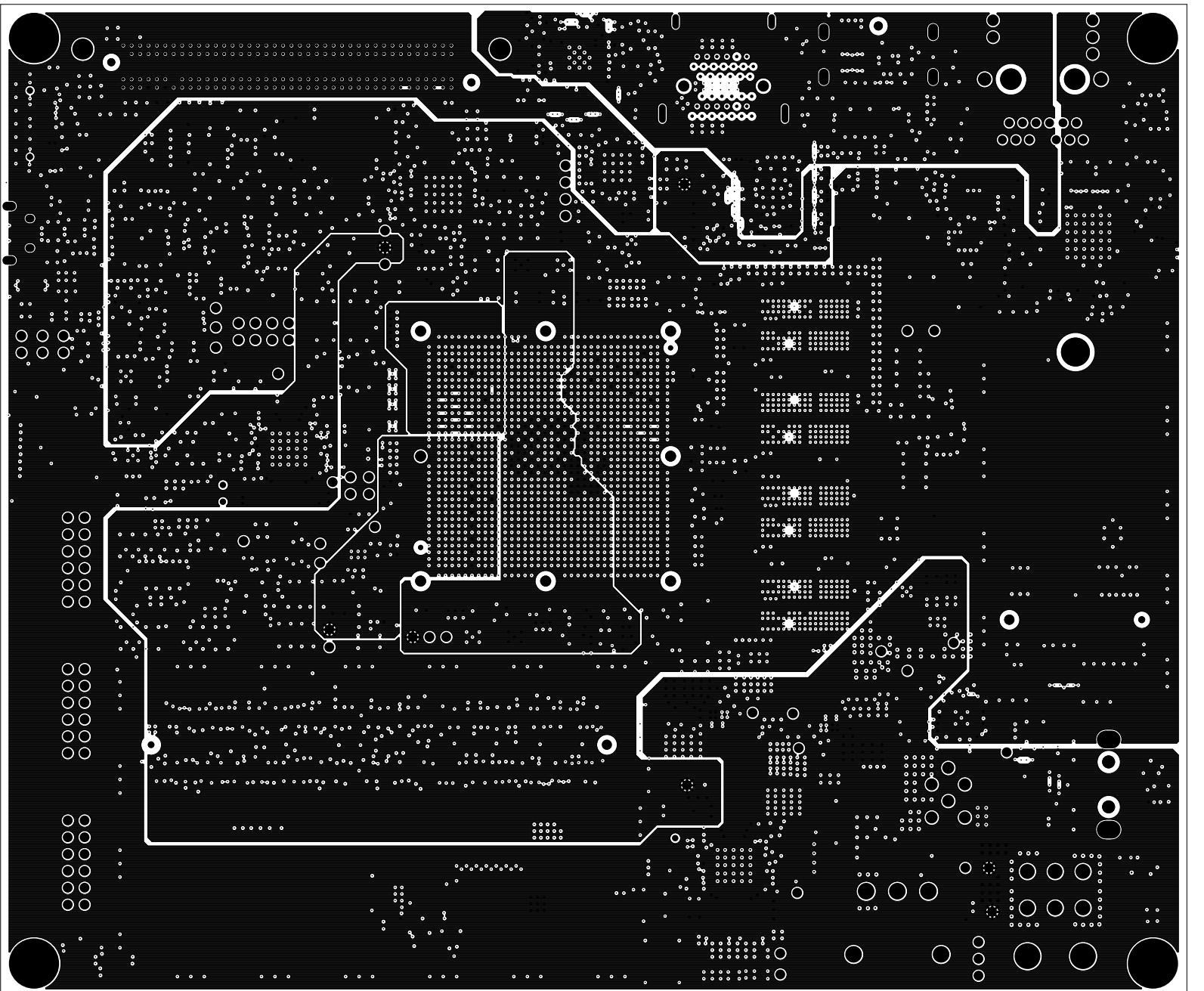
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 07 OF 22 LAYER: SIG3	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



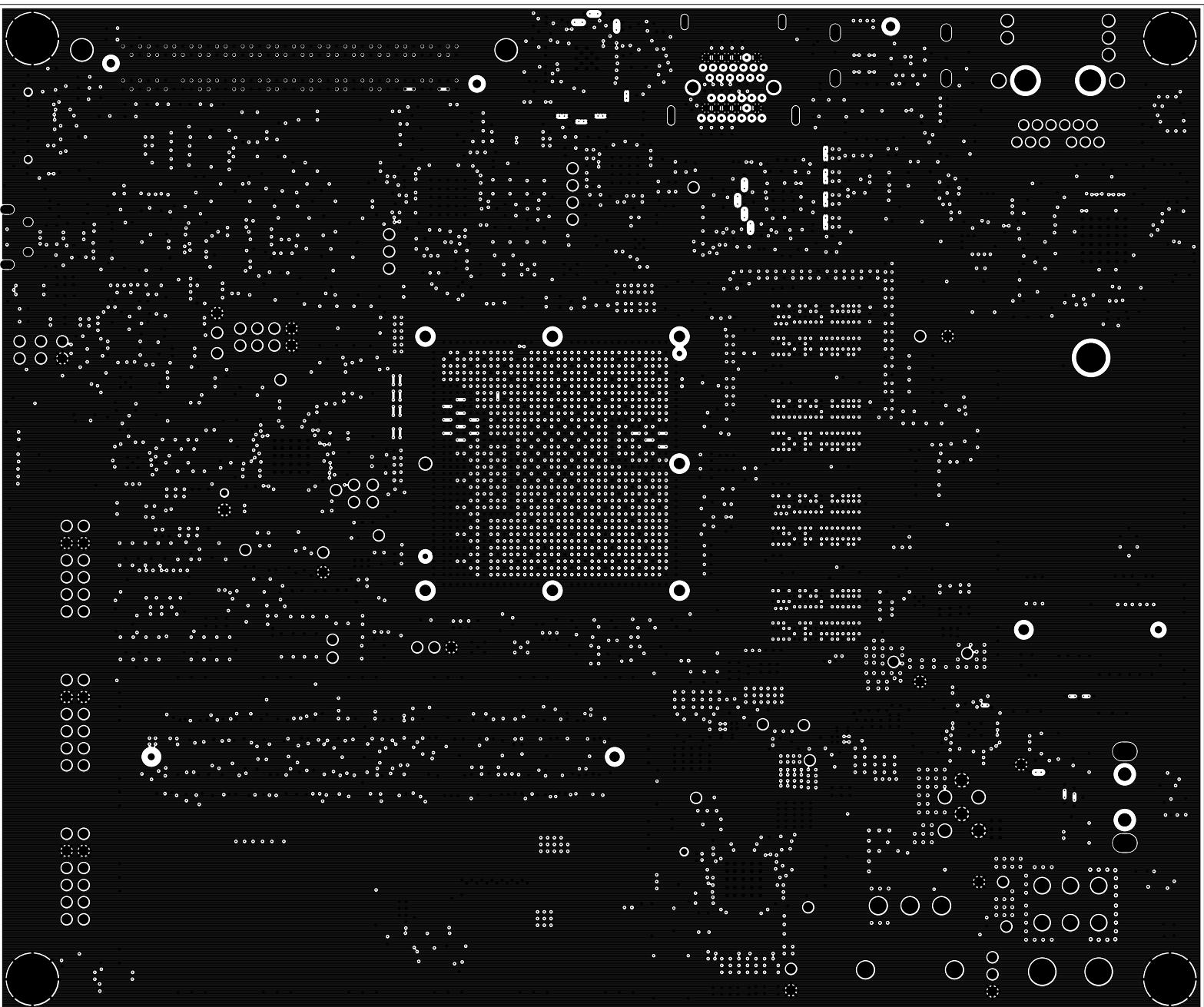
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 08 OF 22 LAYER: GND4	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



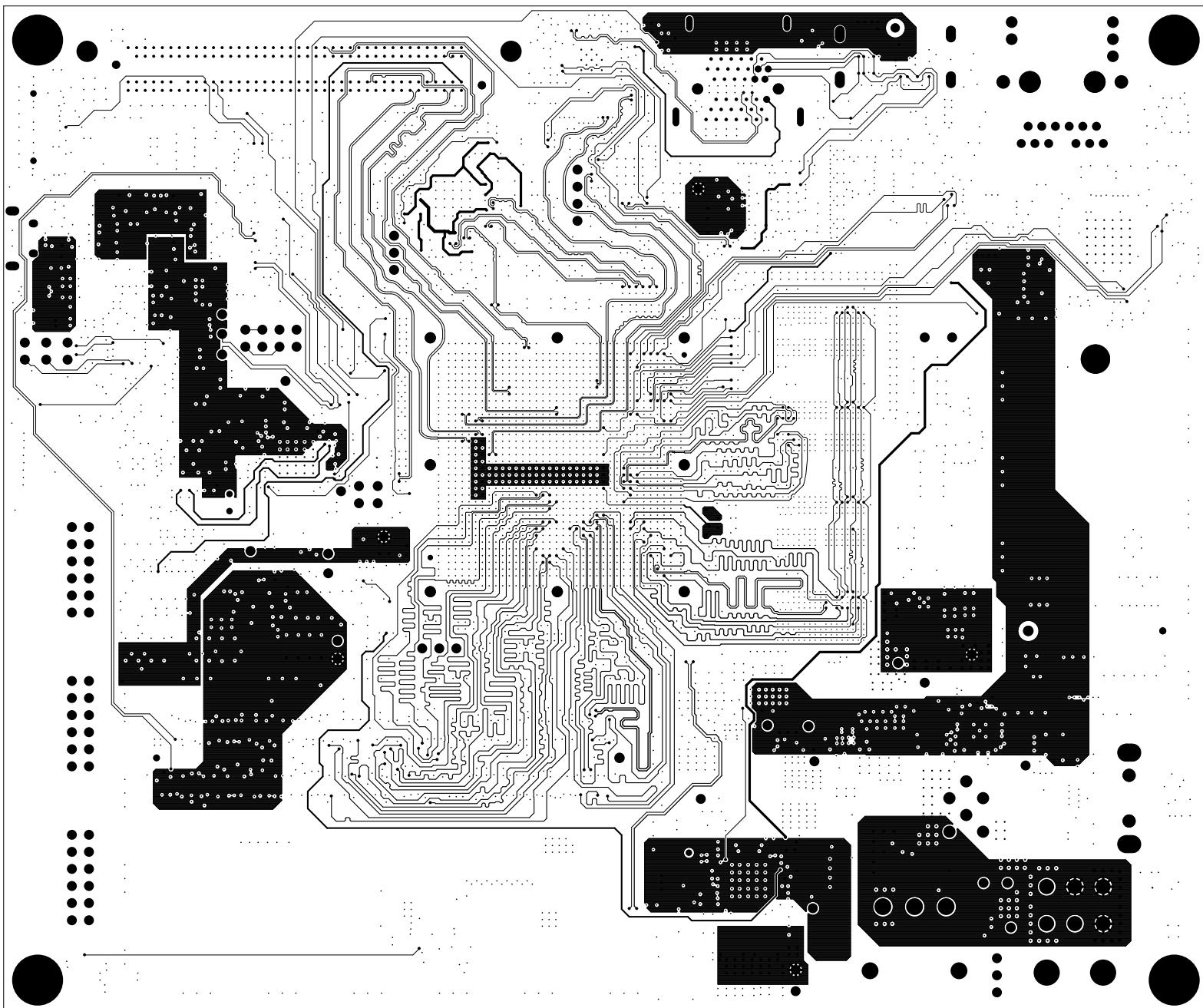
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 09 OF 22 LAYER: PWR1	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



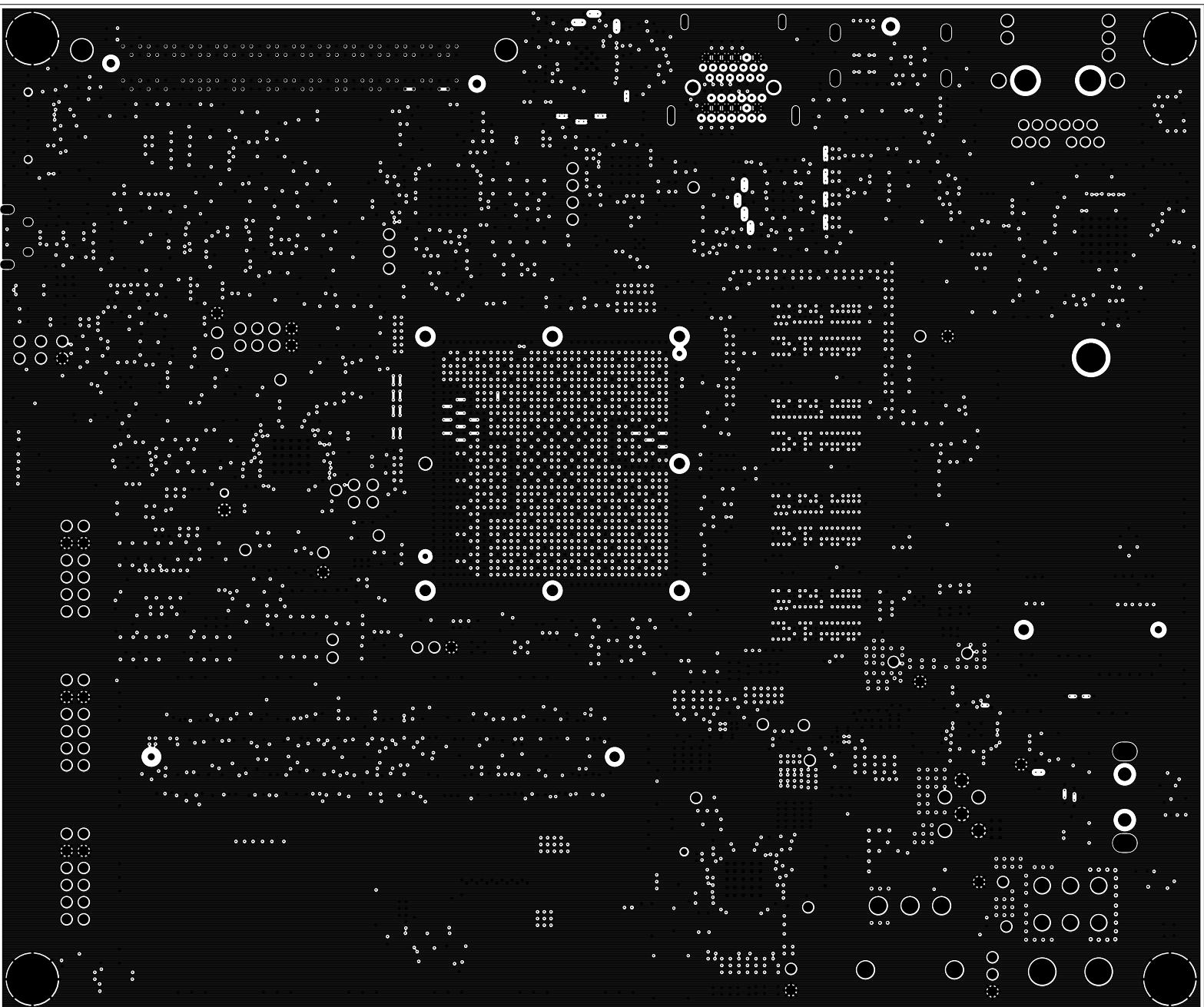
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 10 OF 22 LAYER: PWR2	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



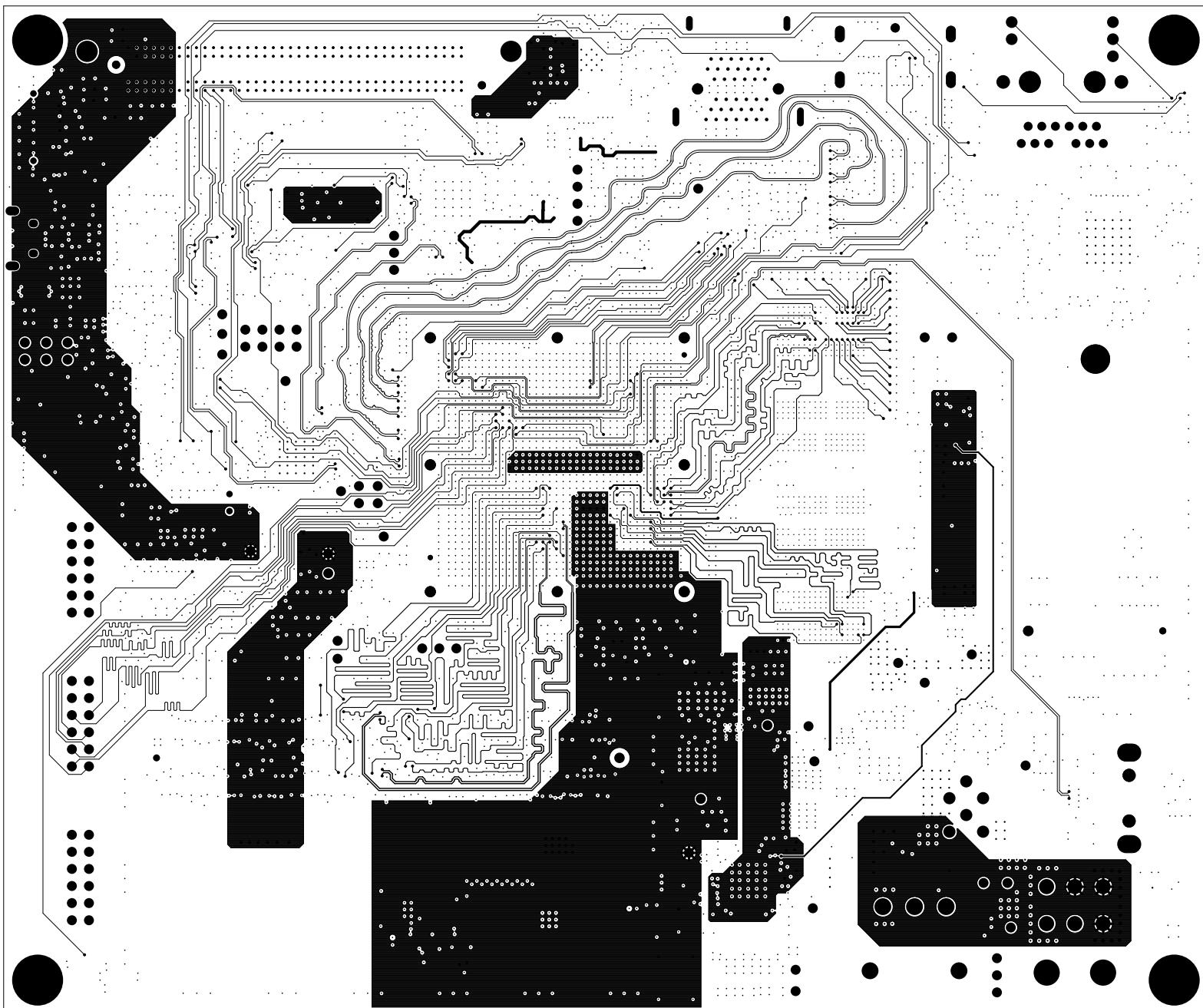
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 11 OF 22 LAYER: GND5	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



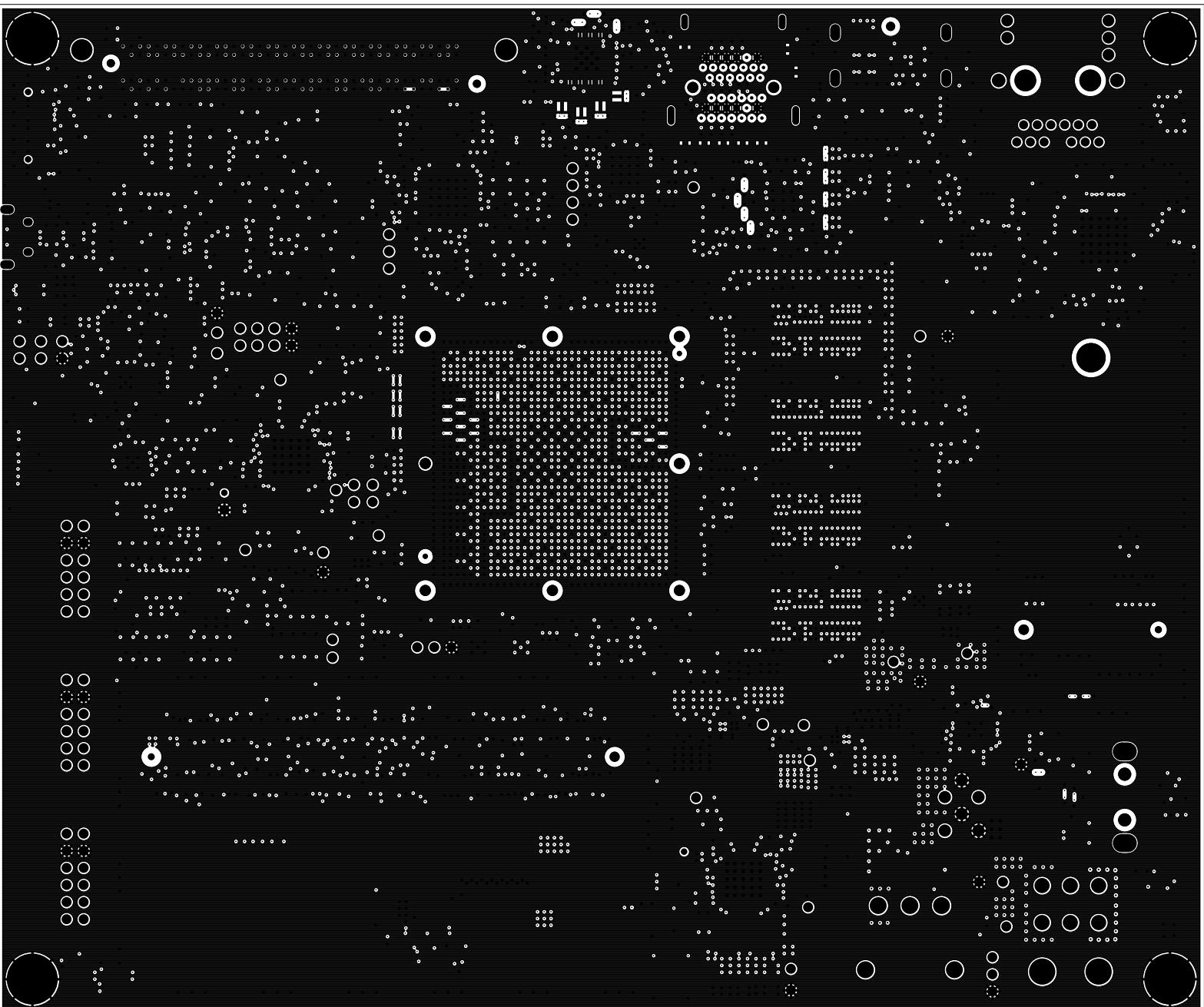
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 12 OF 22 LAYER: SIG4	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



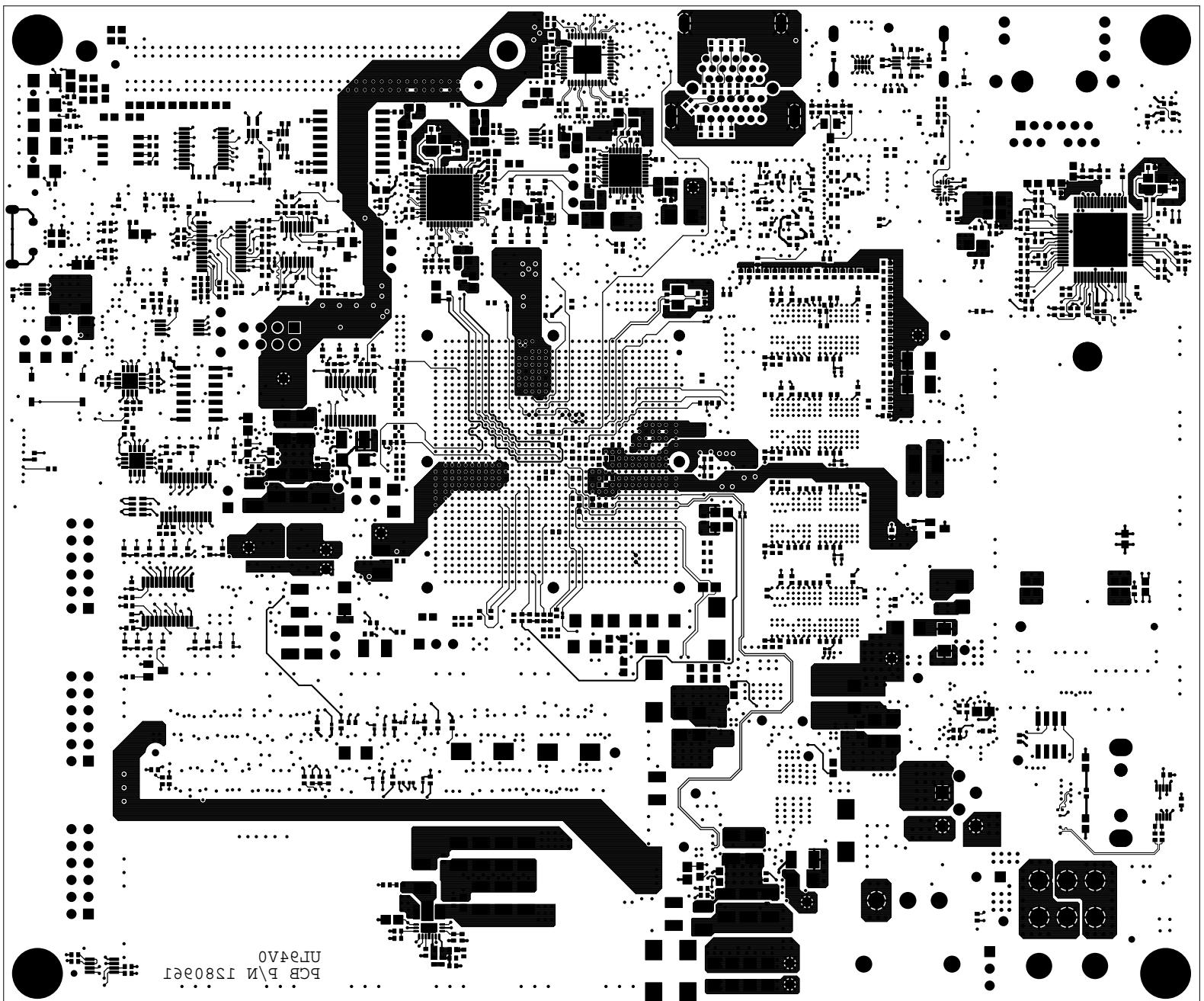
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 13 OF 22 LAYER: GND6	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



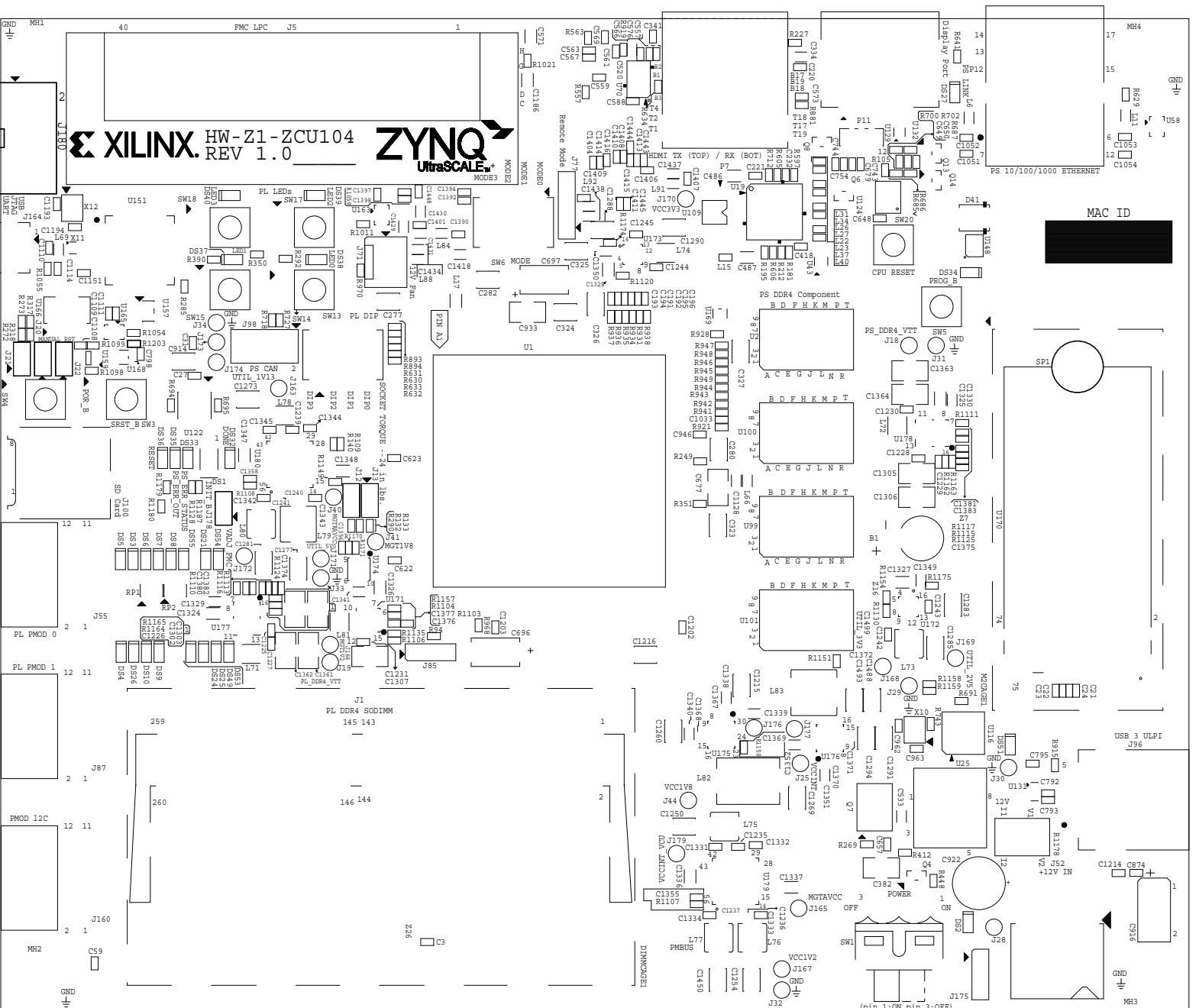
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 14 OF 22 LAYER: SIG5	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



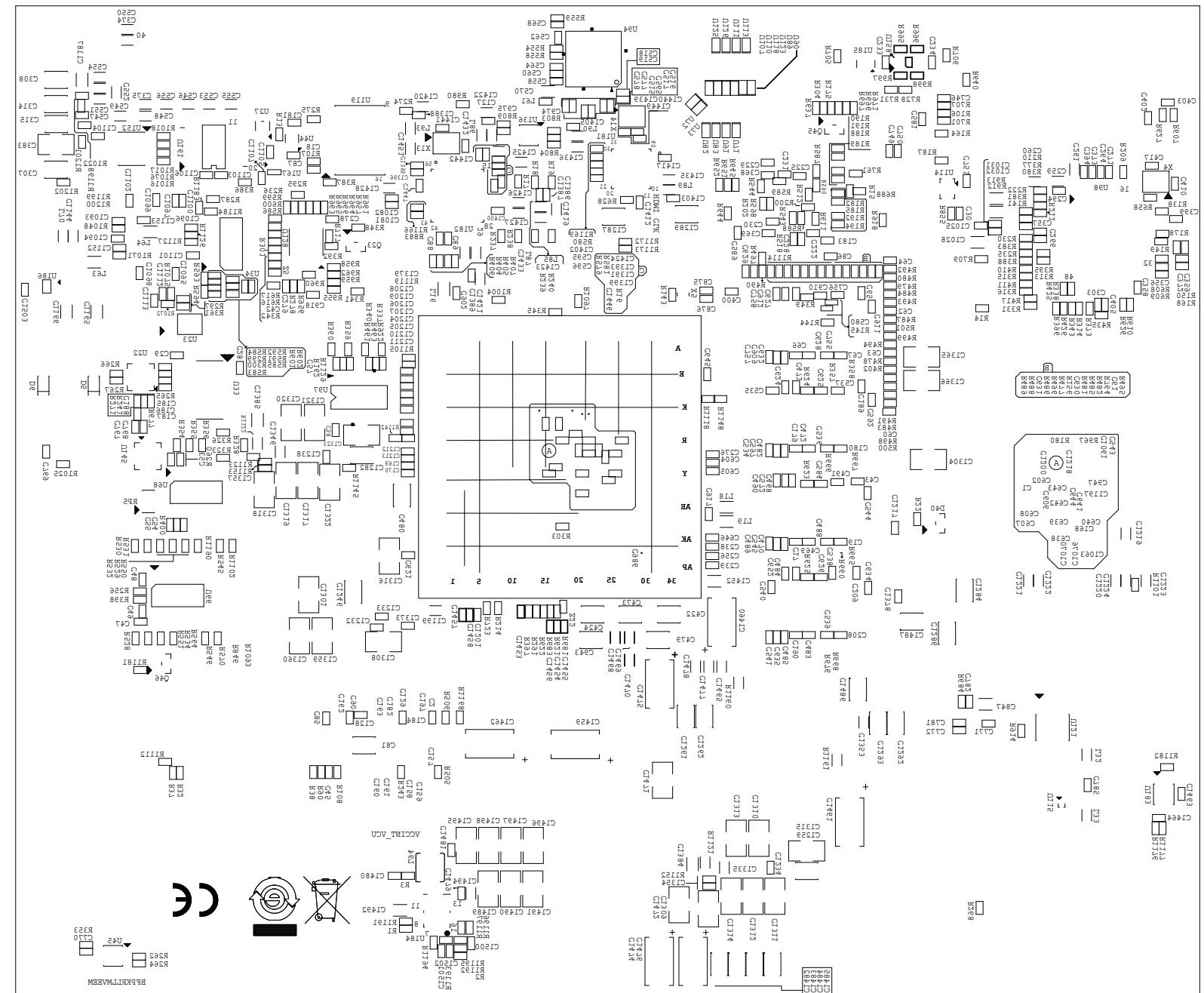
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 15 OF 22 LAYER: GND7	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



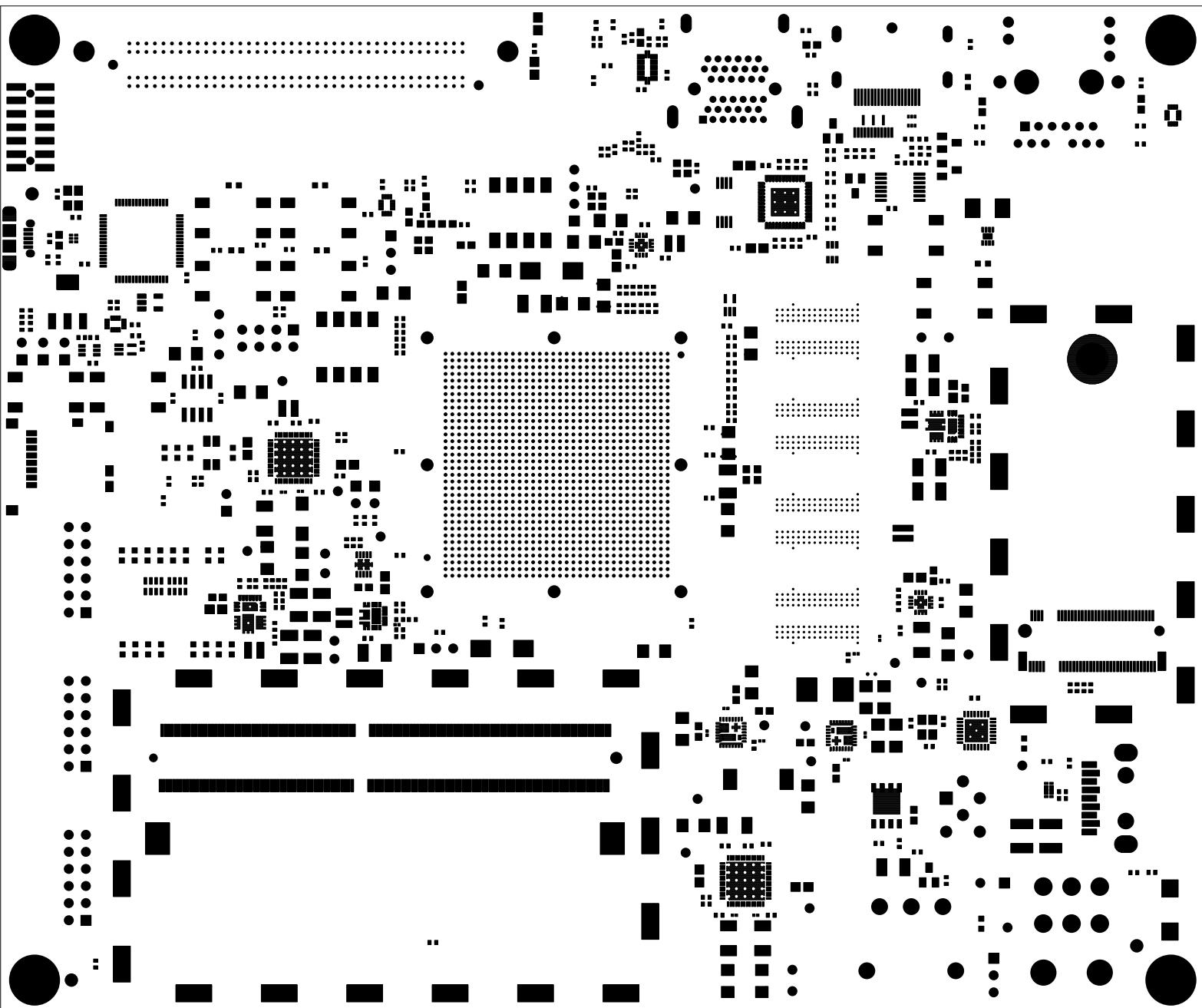
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 16 OF 22 LAYER: BOTTOM	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



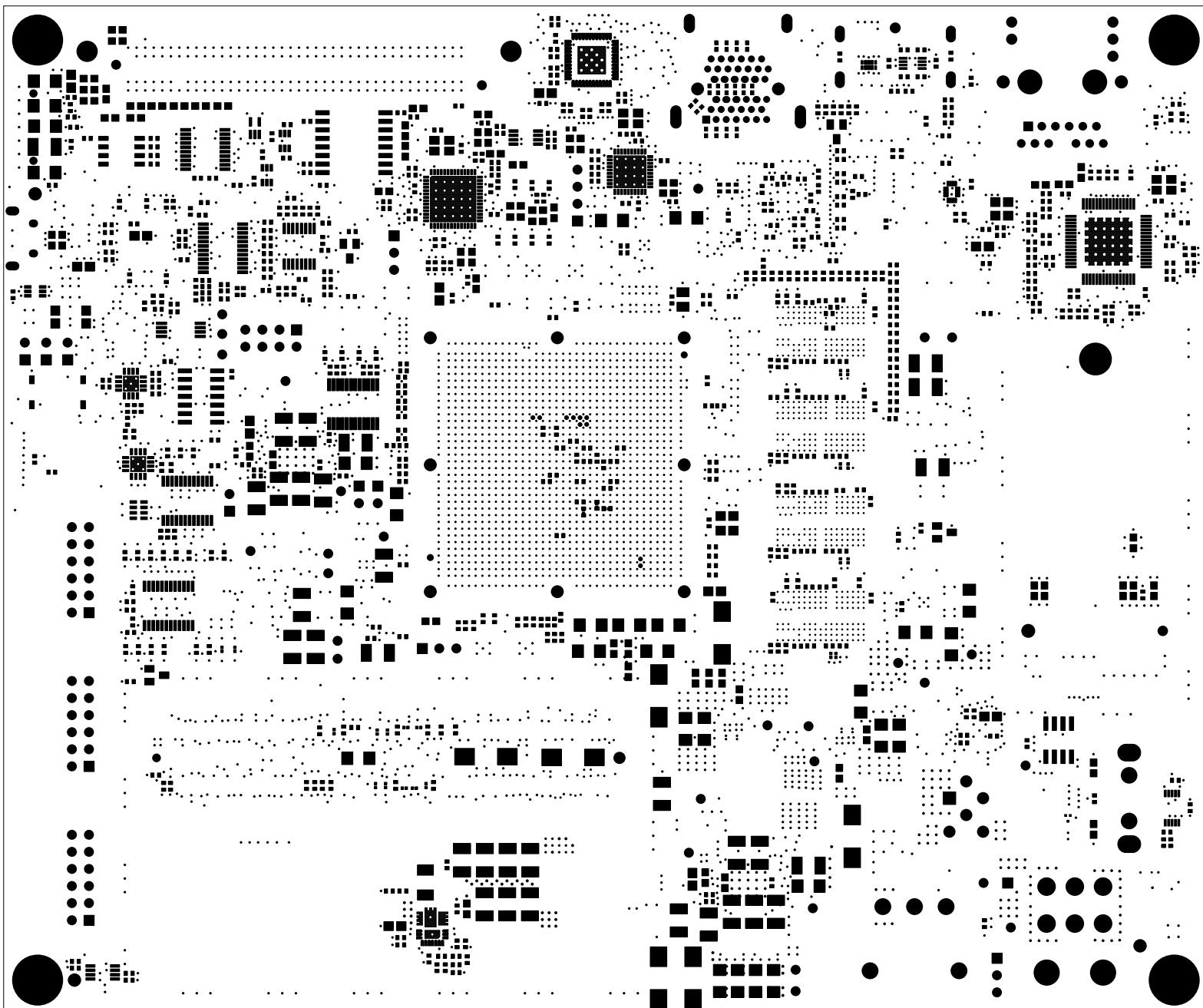
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 17 OF 22 LAYER: 17_SILK_TOP	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



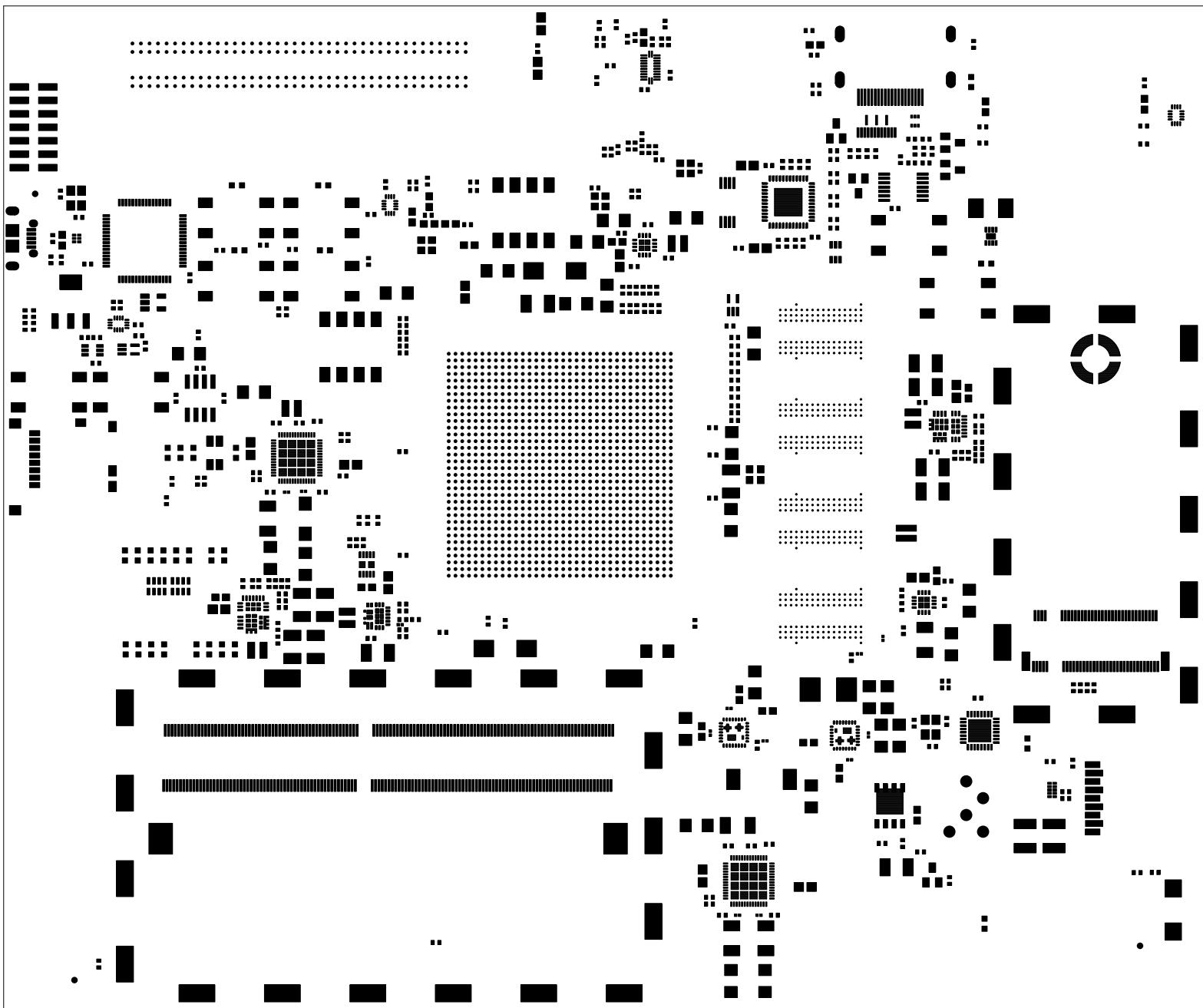
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 18 OF 22 LAYER:18_SILK_BOT	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



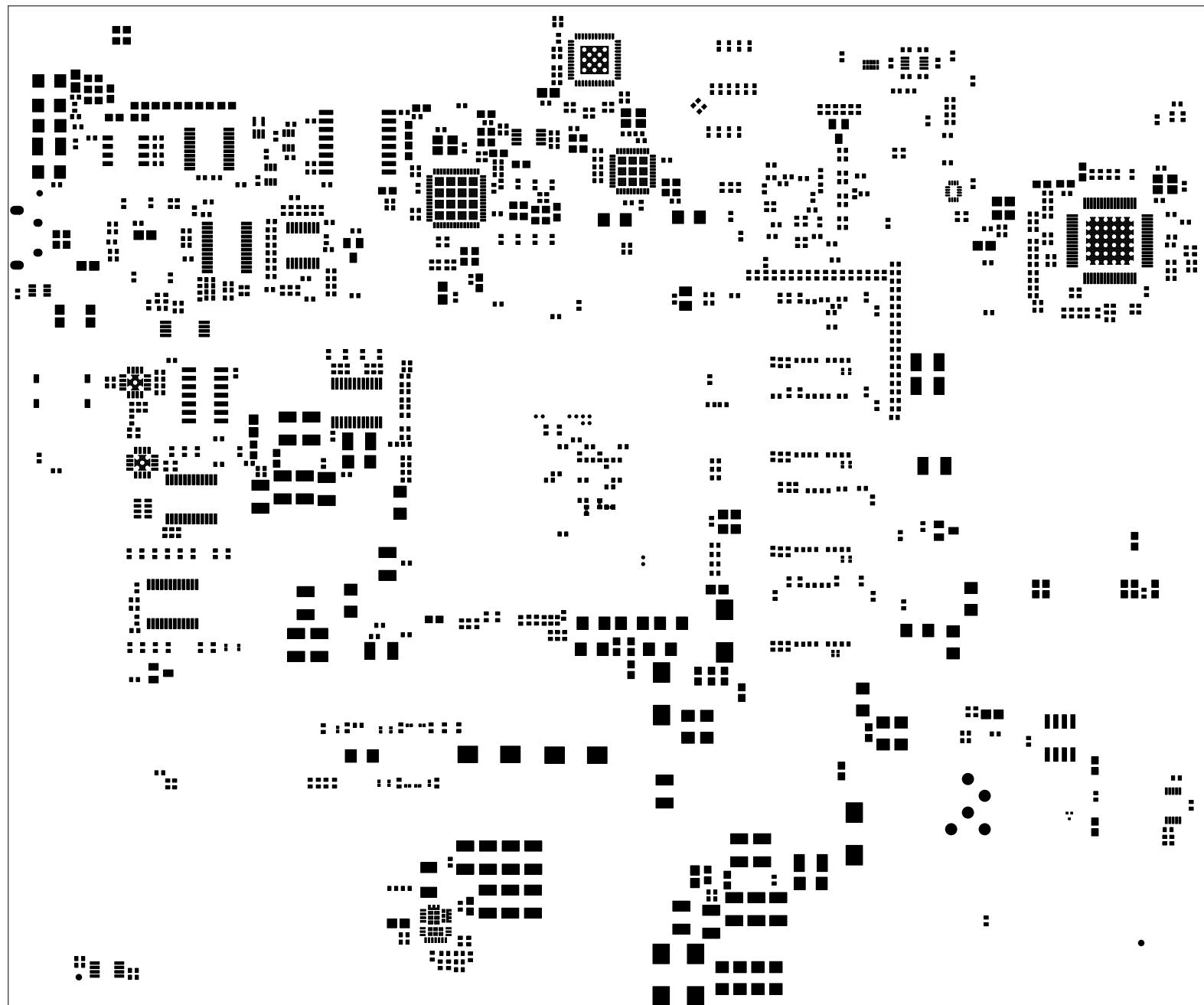
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 19 OF 22 LAYER: 19_SMASK_TOP	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



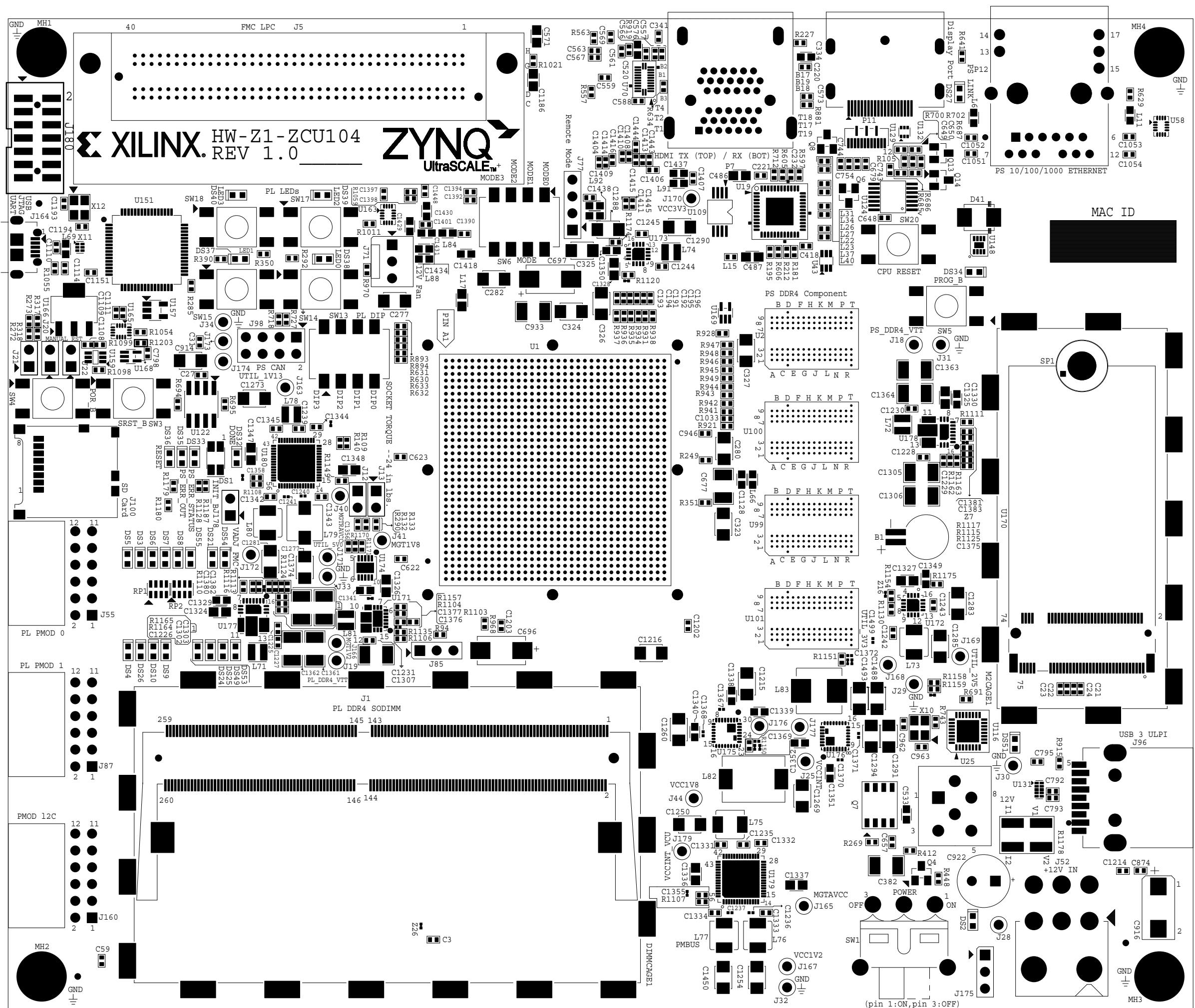
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PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 20 OF 22 LAYER:20_SMASK_BOT	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0

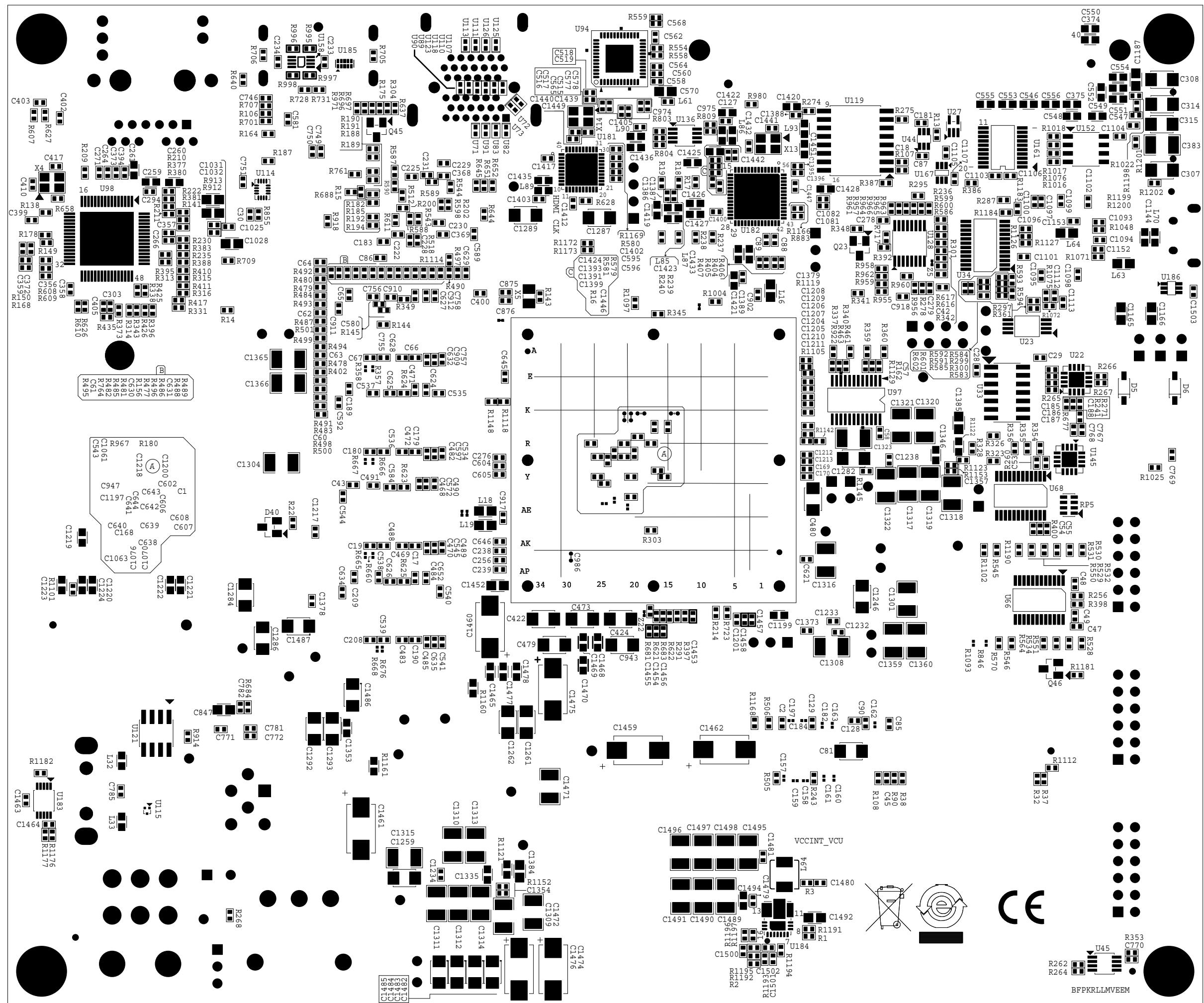


ARTWORK, ROHS COMPLIANT, HW-Z1-ZCU104	
PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 21 OF 22 LAYER: 21_PMASK_TOP	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0



ARTWORK, ROHS COMPLIANT, HW-Z1-ZCU104	
PCB #	1280961
Designed by Xilinx	DATE: 02/10/2018
SCAREY	PHONE: 4088794451
SHEET 22 OF 22 LAYER: 22_PMASK_BOT	XILINX DOC USE ONLY REVISION: 01 VERSION: 1.0





NOTES: (UNLESS OTHERWISE SPECIFIED)

1. ASSEMBLE TO MEET INSPECTION CRITERIA OF IPC-A-610, CLASS 2, CURRENT REVISION.
  2. BAG AND TAG (OR MARK CONTAINER) WITH PART NUMBER.
  3. REFERENCE SCHEMATIC (OR AVL) FOR BILL OF MATERIALS.
  4. ASSEMBLY SHOULD BE "ROHS" AND "LEAD FREE" COMPLIANT.

5. FAB IS BOUND TO USE "SAC305" SOLDER PASTE FOR COMPONENT ASSEMBLY

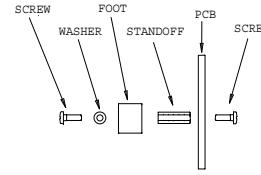
- (c) . MAXIMUM PASTE MASK STENCIL THICKNESS IN THE AREA OF MAXIMUM POWER SUPPLIES (eg HPQFN 19 A DEVICES) MUST BE 4MILS MAX.

7. SERIAL NUMBER INSTRUCTIONS:

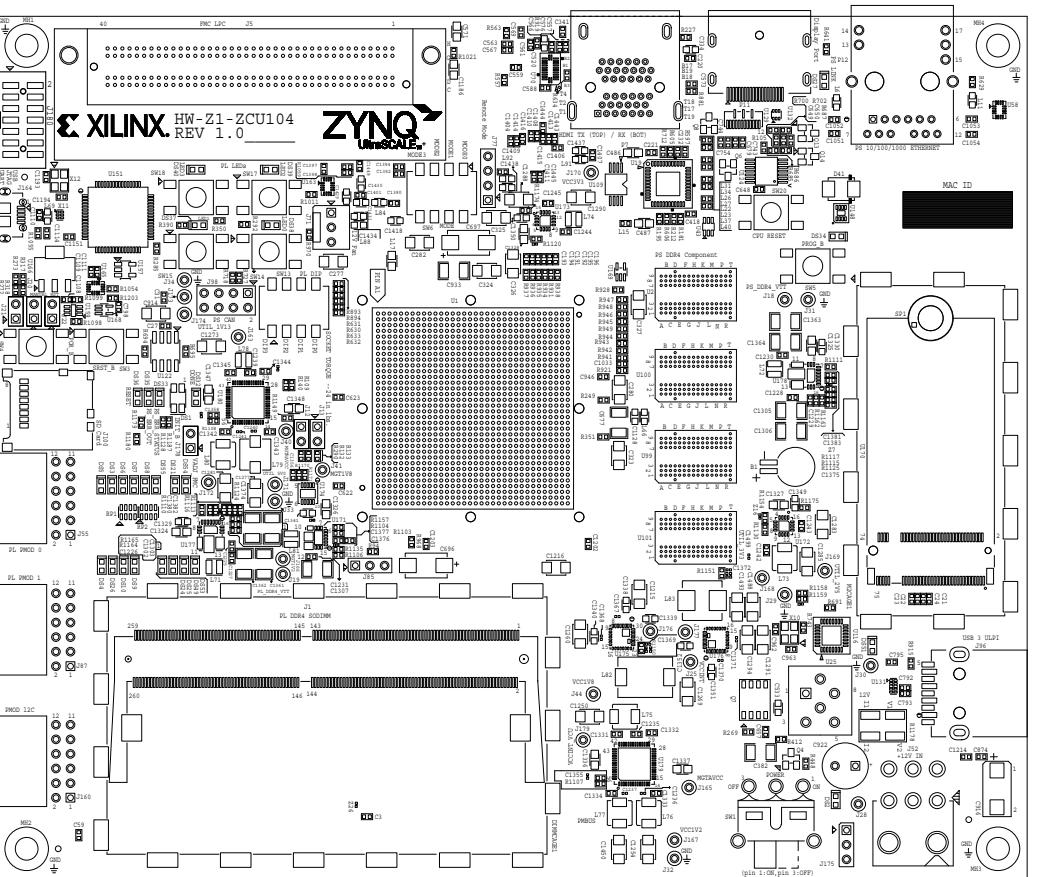
" FOLLOW THE XILINX SERIAL NUMBER CONVENTION. FOR EXAMPLE KCU105 REV A IS NUMBERED 1280723A001 TO 1280723A020, REV B SHOULD START AT 1280723C001 AND END AT 1280723C075"  
END-FILE C IS SHOULD START AT 1280723C001

FOR REV C IT SHOULD START AT 1280723C0  
6. DATA SHEET SHOULD BE FOLLOWED FOR ALL UGM

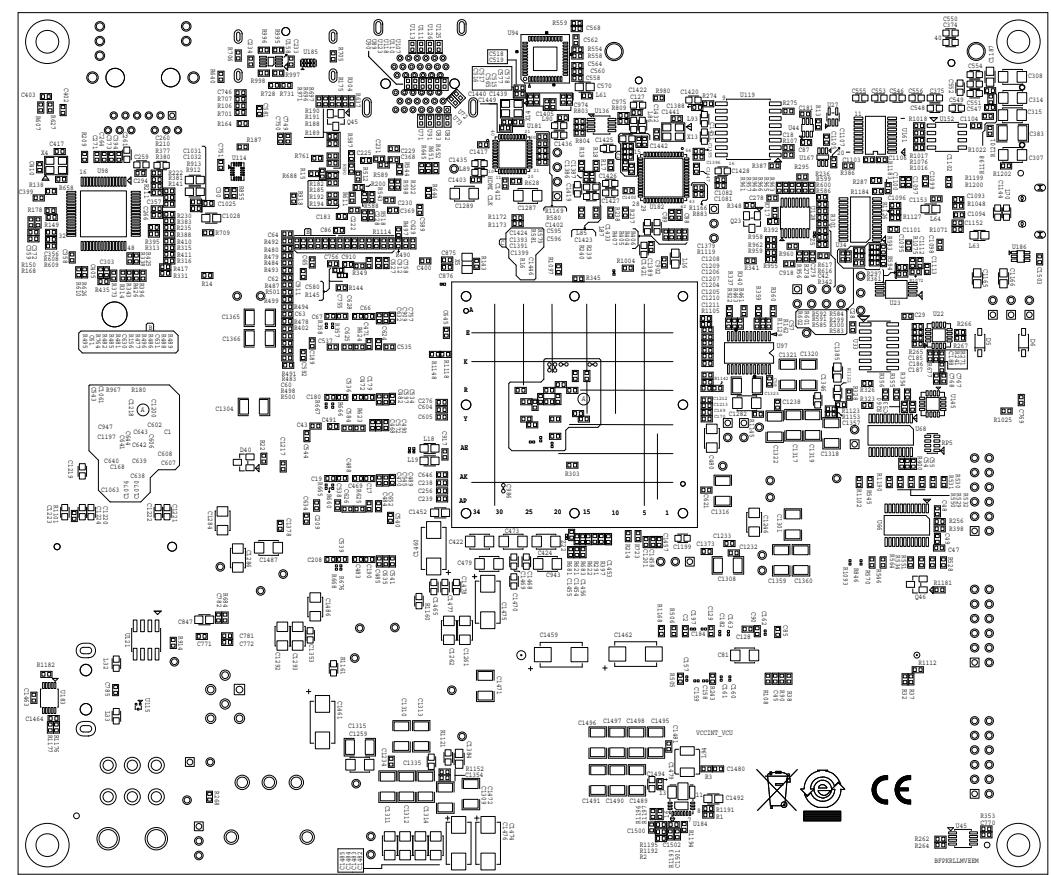
8. DATASHEET SHOULD BE FOLLOWED FOR ALL HSMF-C155 DEVICES.



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
B	PROTOTYPE	08/30/17	
B	PROTOTYPE	08/30/17	
C	PROTOTYPE	11/27/17	
1.0	PROTOTYPE	02/10/18	
01	PROTOTYPE	02/08/18	



VIEWED FROM TOP SIDE



**VIEWED FROM BOTTOM SIDE**

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	 <b>XILINX®</b> 2100 LOGIC DR. SAN JOSE, CA 95124 HWCP - HARDWARE & CONFIGURATION PLATFORMS				
DIMENSIONS ARE IN INCHES	DRAWN	Rocket EMS	02-10-18	<b>ASSEMBLY DRAWING</b>  <b>HW-Z1-ZCU104</b>			
TOLERANCES ON;	CHECKED	Brian Forsse					
2 PL DECIMALS +/- .010	ENGRG	Brian Forsse	02-10-18				
3 PL DECIMALS +/- .005	ISSUED						
ANGLES +							
FRACTIONS +				SIZE <b>D</b>	FSCM NO <b>0432057</b>	DWG NO <b>0432057</b>	REV: 01
							VER: 1.0
				SCALE	NONE		SHEET 1 OF 1